

XC866

8-Bit Single-Chip Microcontroller

Preliminary

8bit

Microcontrollers



Never stop thinking.

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XC866 Data Sheet
Advance Information

Revision History: 2005-02

V0.1

Previous Version:

Page	Subjects (major changes since last revision)

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8-Bit Single-Chip Microcontroller XC800 Family

XC866

Advance Information

- High-performance XC800 Core
 - compatible with standard 8051 processor
 - two clocks per machine cycle architecture (for memory access without wait state)
 - two data pointers
- On-chip memory
 - 8 Kbytes of Boot ROM
 - 256 bytes of RAM
 - 512 bytes of XRAM
 - 8/16 Kbytes of Flash; or
8/16 Kbytes of ROM, with additional 4 Kbytes of Flash
- I/O port supply at 3.3 to 5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)
- Power-on reset generation
- Brownout detection for core logic supply
- On-chip OSC and PLL for clock generation
 - PLL loss-of-lock detection

(further features are on next page)

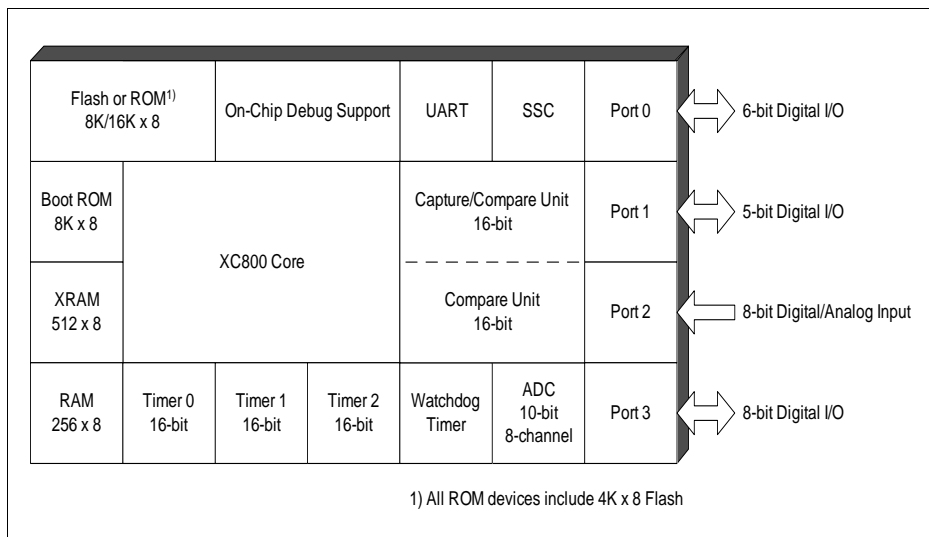


Figure 1 XC866 Functional Units

Features (continued):

- Power saving modes
 - slow-down mode
 - idle mode
 - power-down mode with wake-up capability via RXD or EXINT0
 - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
 - 19 pins as digital I/O
 - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
 - Timer 0 and Timer 1 (T0 and T1)
 - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
 - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
 - 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range T_A :
 - SAF (-40 to 85 °C)
 - SAK (-40 to 125 °C)

XC866 Variant Devices

The XC866 product family features eight devices with different configurations and program memory sizes, offering cost-effective solution for different application requirements.

The list of XC866 devices and their differences are summarized in [Table 1](#).

Table 1 Device Summary

Device Type	Device Name	Flash Size	ROM Size	LIN Support
Flash	XC866L-4FR	16 Kbytes	–	Yes
	XC866-4FR	16 Kbytes	–	No
	XC866L-2FR	8 Kbytes	–	Yes
	XC866-2FR	8 Kbytes	–	No
ROM	XC866L-4RR	4 Kbytes	16 Kbytes	Yes
	XC866-4RR	4 Kbytes	16 Kbytes	No
	XC866L-2RR	4 Kbytes	8 Kbytes	Yes
	XC866-2RR	4 Kbytes	8 Kbytes	No

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set
- the specified temperature range
- the package and the type of delivery

For the available ordering codes for the XC866, please refer to the “**Product Information Microcontrollers**” which summarizes all available microcontroller variants.

Note: The ordering codes for the Mask-ROM versions are defined for each product after verification of the respective ROM code.

Block Diagram

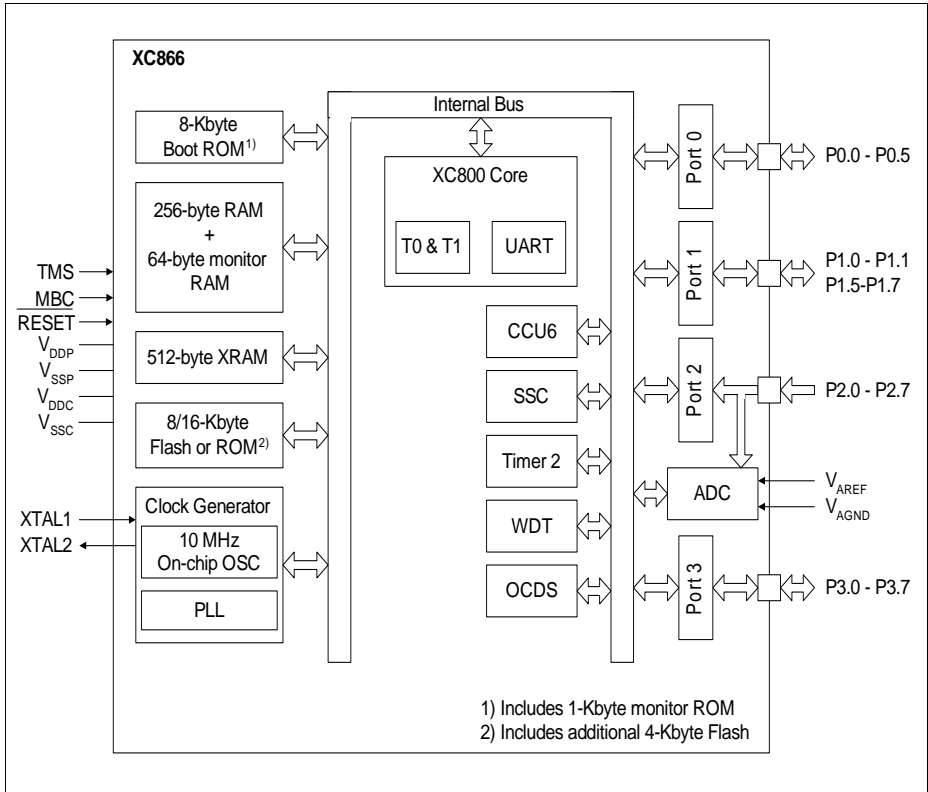


Figure 2 XC866 Block Diagram

Logic Symbol

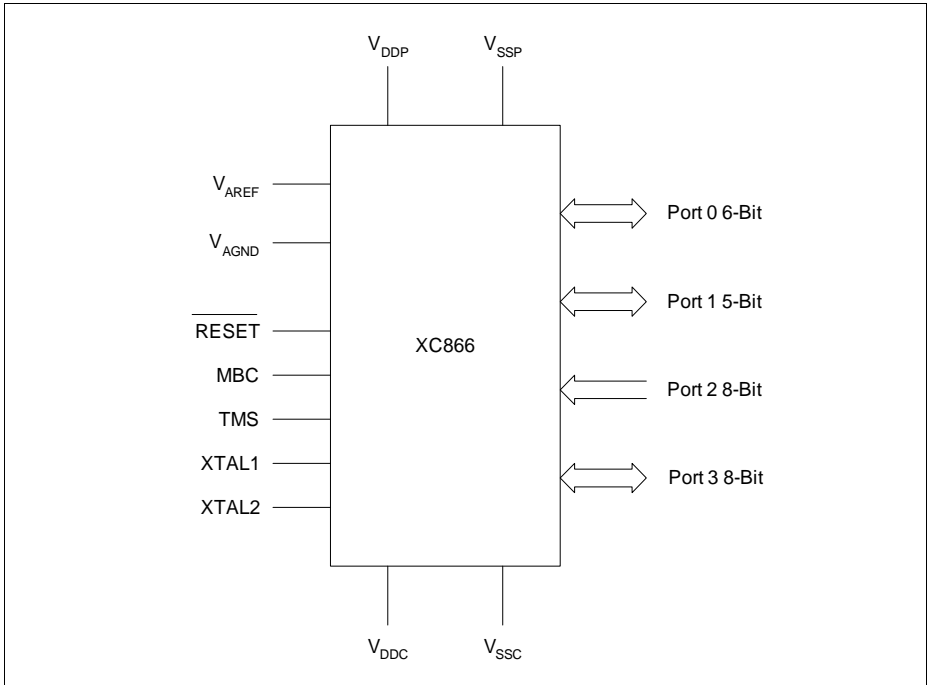


Figure 3 XC866 Logic Symbol

Pin Configuration

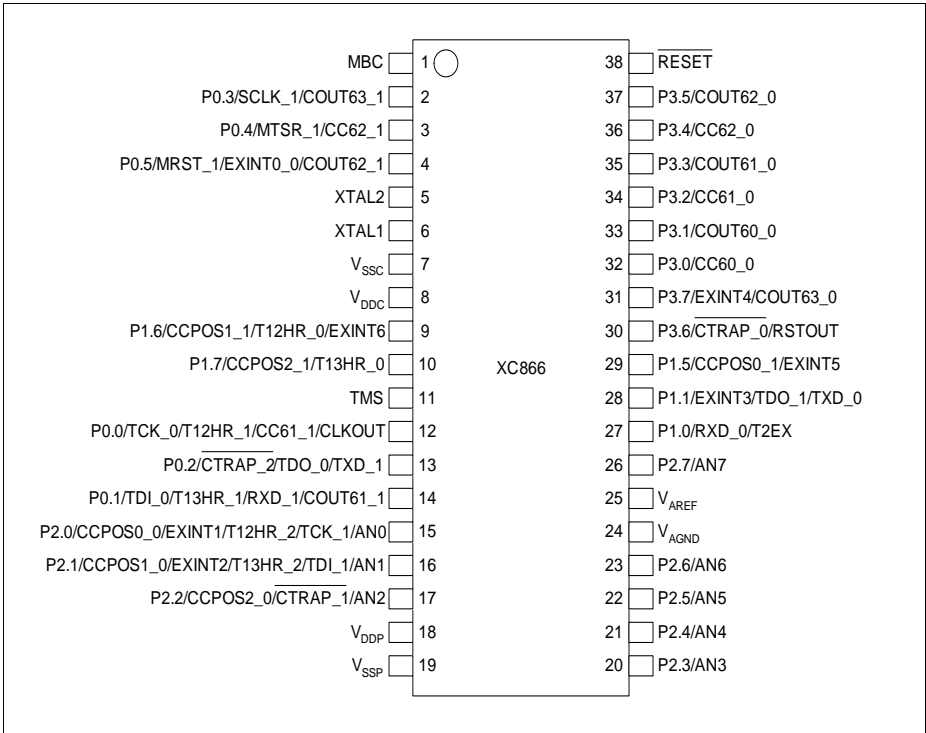


Figure 4 XC866 Pin Configuration, PG-TSSOP-38 Package (top view)

Table 2 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State	Function
P0		I/O		Port 0 Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P0.0	12		Hi-Z	TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT 10 MHz On-Chip OSC Clock Output
P0.1	14		Hi-Z	TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Input COUT61_1 Output of Capture/Compare channel 1
P0.2	13		PU	CTRAP_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Output
P0.3	2		Hi-Z	SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3
P0.4	3		Hi-Z	MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2
P0.5	4		Hi-Z	MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P1		I/O		Port 1 Port 1 is a 5-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P1.0	27		PU	RXD_0 UART Receive Input T2EX Timer 2 External Trigger Input
P1.1	28		PU	EXINT3 External Interrupt Input 3 TDO_1 JTAG Serial Data Output TXD_0 UART Transmit Output
P1.5	29		PU	CCPOS0_1 CCU6 Hall Input 0 EXINT5 External Interrupt Input 5
P1.6	9		PU	CCPOS1_1 CCU6 Hall Input 1 T12HR_0 CCU6 Timer 12 Hardware Run Input
P1.7	10		PU	EXINT6 External Interrupt Input 6 CCPOS2_1 CCU6 Hall Input 2 T13HR_0 CCU6 Timer 13 Hardware Run Input
				P1.5 and P1.6 can be used as a software chip select output for the SSC.

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P2		I		Port 2 Port 2 is an 8-bit general purpose input-only port. It can be used as alternate functions for the digital inputs of the JTAG and CCU6. It is also used as the analog inputs for the ADC.
P2.0	15	Hi-Z		CCPOS0_0 CCU6 Hall Input 0 EXINT1 External Interrupt Input 1 T12HR_2 CCU6 Timer 12 Hardware Run Input TCK_1 JTAG Clock Input AN0 Analog Input 0
P2.1	16	Hi-Z		CCPOS1_0 CCU6 Hall Input 1 EXINT2 External Interrupt Input 2 T13HR_2 CCU6 Timer 13 Hardware Run Input TDI_1 JTAG Serial Data Input AN1 Analog Input 1
P2.2	17	Hi-Z		CCPOS2_0 CCU6 Hall Input 2 CTRAP_1 CCU6 Trap Input AN2 Analog Input 2
P2.3	20	Hi-Z		AN3 Analog Input 3
P2.4	21	Hi-Z		AN4 Analog Input 4
P2.5	22	Hi-Z		AN5 Analog Input 5
P2.6	23	Hi-Z		AN6 Analog Input 6
P2.7	26	Hi-Z		AN7 Analog Input 7

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P3		I		Port 3 Port 3 is a bidirectional general purpose I/O port. It can be used as alternate functions for the CCU6.
P3.0	32		Hi-Z	CC60_0 Input/Output of Capture/Compare channel 0
P3.1	33		Hi-Z	COU60_0 Output of Capture/Compare channel 0
P3.2	34		Hi-Z	CC61_0 Input/Output of Capture/Compare channel 1
P3.3	35		Hi-Z	COU61_0 Output of Capture/Compare channel 1
P3.4	36		Hi-Z	CC62_0 Input/Output of Capture/Compare channel 2
P3.5	37		Hi-Z	COU62_0 Output of Capture/Compare channel 2
P3.6	30		PD	$\overline{\text{CTRAP}}_0$ CCU6 Trap Input RSTOUT Reset output indication for internal reset condition in microcontroller
P3.7	31		Hi-Z	EXINT4 External Interrupt Input 4 COU63_0 Output of Capture/Compare channel 3

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
V_{DDP}	18	–	–	I/O Port Supply (3.3 - 5.0 V)
V_{SSP}	19	–	–	I/O Port Ground
V_{DDC}	8	–	–	Core Supply Monitor (2.5 V)
V_{SSC}	7	–	–	Core Supply Ground
V_{AREF}	25	–	–	ADC Reference Voltage
V_{AGND}	24	–	–	ADC Reference Ground
XTAL1	6	I	Hi-Z	External Oscillator Input (backup for on-chip OSC, normally NC)
XTAL2	5	O	Hi-Z	External Oscillator Output (backup for on-chip OSC, normally NC)
TMS	11	I	PD	Test Mode Select
RESET	38	I	PU	Reset Input for PG-TSSOP-38 package
MBC	1	I	PU	Monitor & BootStrap Loader Control

Processor Architecture

The XC866 is based on a high-performance 8-bit Central Processing Unit (CPU) that is compatible with the standard 8051 processor. While the standard 8051 processor is designed around a 12-clock machine cycle, the XC866 CPU uses a 2-clock machine cycle. This allows fast access to ROM or RAM memories without wait state. Access to the Flash memory, however, requires an additional wait state (one machine cycle). The instruction set consists of 45% one-byte, 41% two-byte and 14% three-byte instructions.

The XC866 CPU provides a range of debugging features, including basic stop/start, single-step execution, breakpoint support and read/write access to the data memory, program memory and SFRs.

Figure 5 shows the CPU functional blocks.

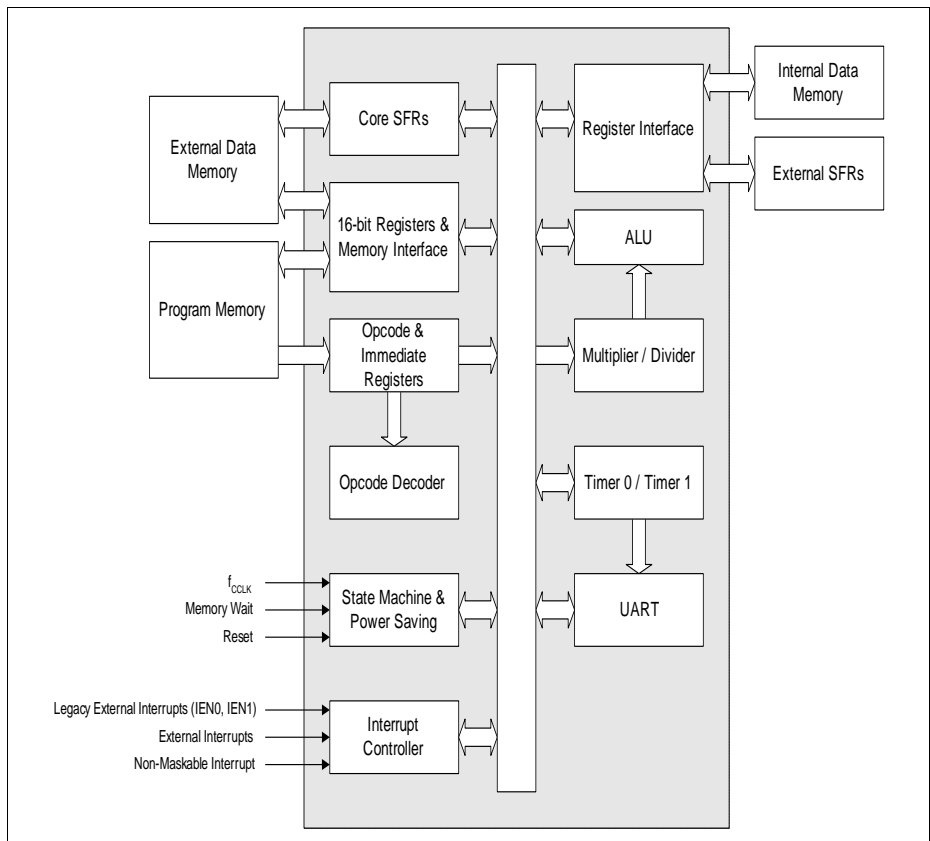


Figure 5 CPU Block Diagram

Memory Organization

The XC866 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM program memory
- 256 bytes of internal RAM data memory
- 512 bytes of XRAM memory
(XRAM can be read/written as program memory or external data memory)
- a 128-byte Special Function Register area
- 8/16 Kbytes of Flash program memory (Flash devices); or
8/16 Kbytes of ROM program memory, with additional 4 Kbytes of Flash (ROM devices)

Figure 6 illustrates the memory address spaces of the 16-Kbyte Flash devices. For the 8-Kbyte Flash devices, the shaded banks are not available.

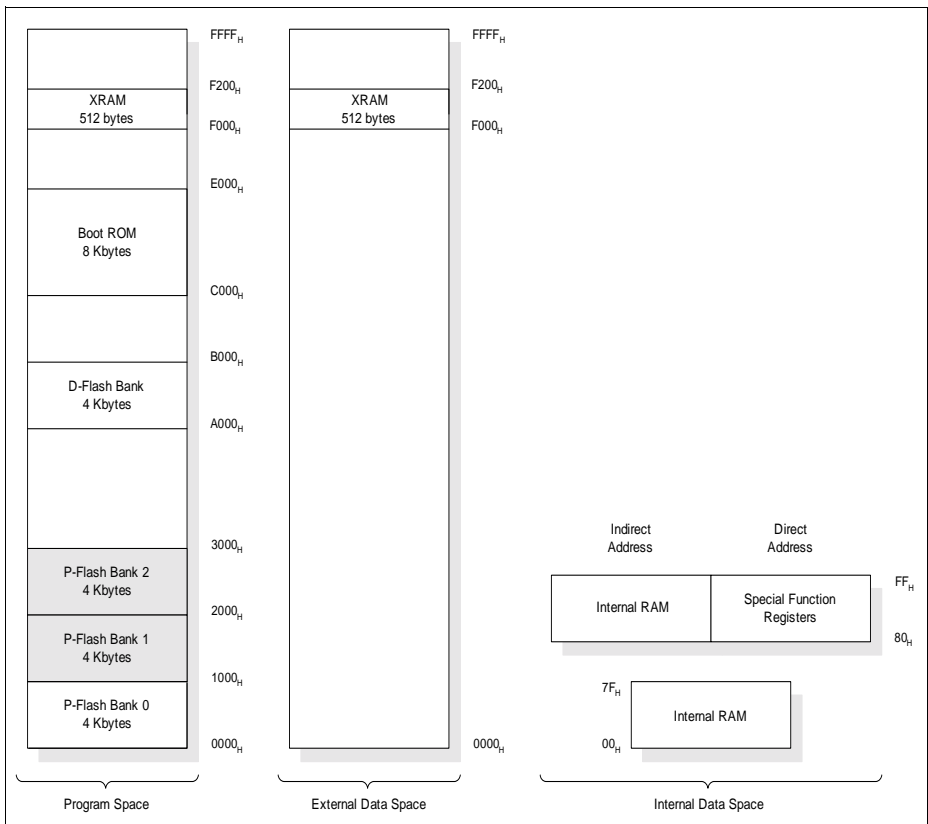


Figure 6 Memory Map of XC866 Flash Device

Figure 7 illustrates the memory address spaces of the 16-Kbyte ROM devices. For the 8-Kbyte ROM devices, the shaded address regions are not available.

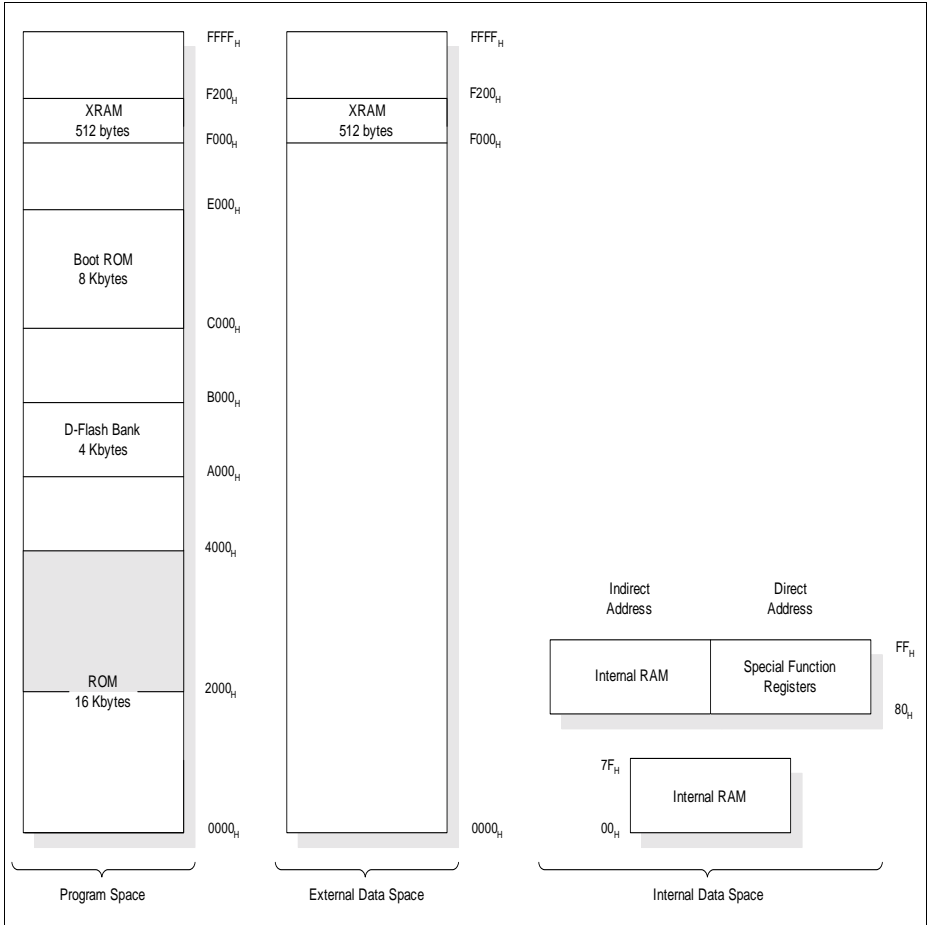


Figure 7 Memory Map of XC866 ROM Device

Special Function Register

The Special Function Registers (SFRs) occupy direct internal data memory space in the range 80_H to FF_H. All registers, except the program counter, reside in the SFR area. The SFRs include pointers and registers that provide an interface between the CPU and the on-chip peripherals. As the 128-SFR range is less than the total number of registers required, address extension mechanisms are required to increase the number of addressable SFRs. The address extension mechanisms include:

- Mapping
- Paging

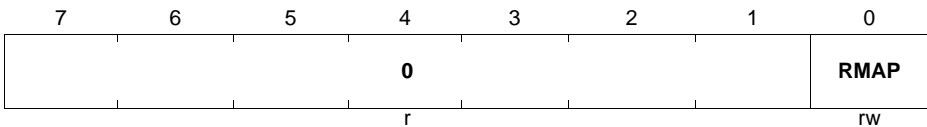
Address Extension by Mapping

Address extension is performed at the system level by mapping. The SFR area is extended into two portions: the standard (non-mapped) SFR area and the mapped SFR area. Each portion supports the same address range 80_H to FF_H, bringing the number of addressable SFRs to 256. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit RMAP in the system control register SYSCON0 at address 8F_H. To access SFRs in the mapped area, bit RMAP in SFR SYSCON0 must be set. Alternatively, the SFRs in the standard area can be accessed by clearing bit RMAP. The SFR area can be selected as shown in **Figure 8**.

SYSCON0

System Control Register 0

Reset Value: 00_H



Field	Bits	Type	Description
RMAP	0	rw	Special Function Register Map Control 0 The access to the standard SFR area is enabled. 1 The access to the mapped SFR area is enabled.
0	[7:1]	r	Reserved Returns 0 if read; should be written with 0.

As long as bit RMAP is set, the mapped SFR area can be accessed. This bit is not cleared automatically by hardware. Thus, before standard/mapped registers are accessed, bit RMAP must be cleared/set, respectively, by software.

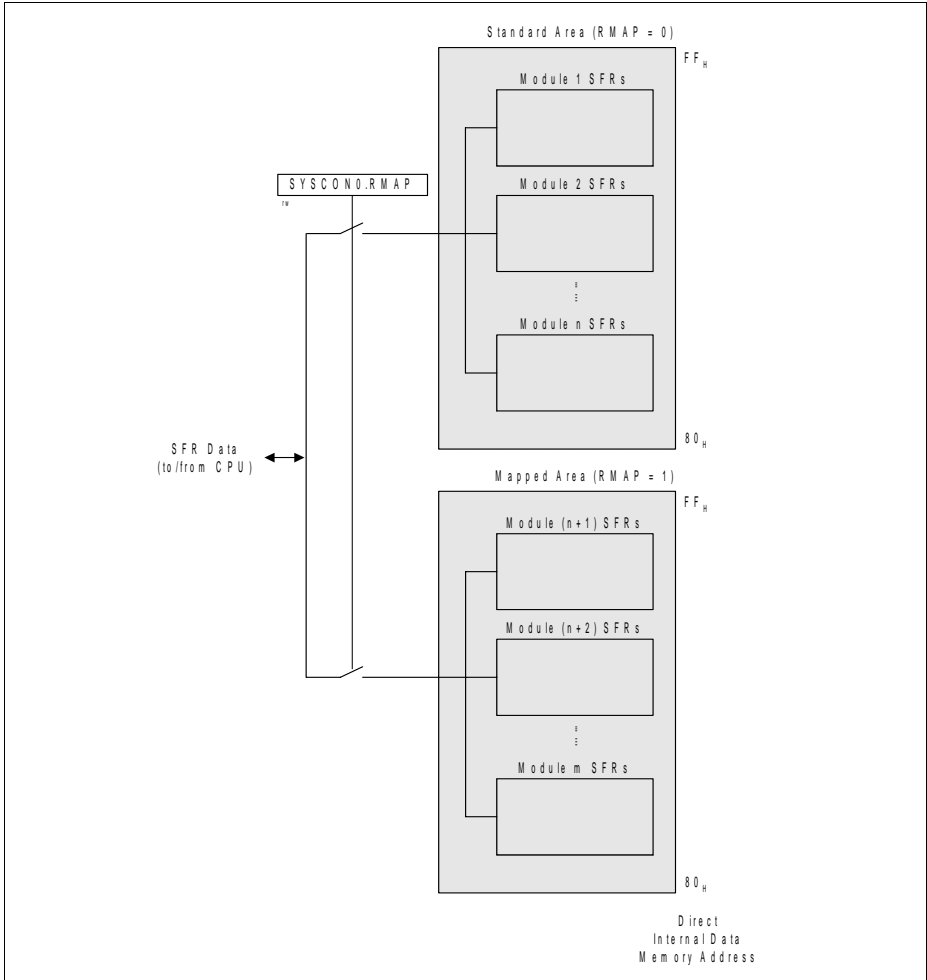


Figure 8 Address Extension by Mapping

Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the XC866 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in **Figure 9**.

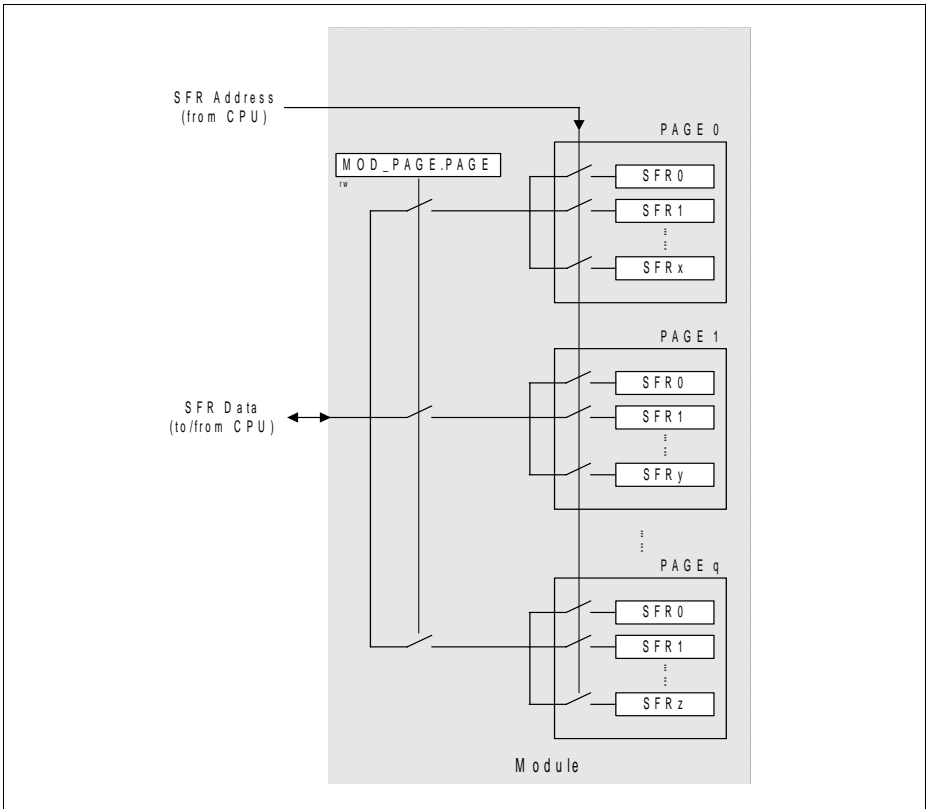


Figure 9 Address Extension by Paging

In order to access a register located in a page different from the actual one, the current page must be left. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and finally, the old page setting restored. This is possible with the storage fields STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in STx before overwriting with the new value (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or
- Overwrite the contents of PAGE with the contents of STx, ignoring the value written to the bit positions of PAGE (this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)

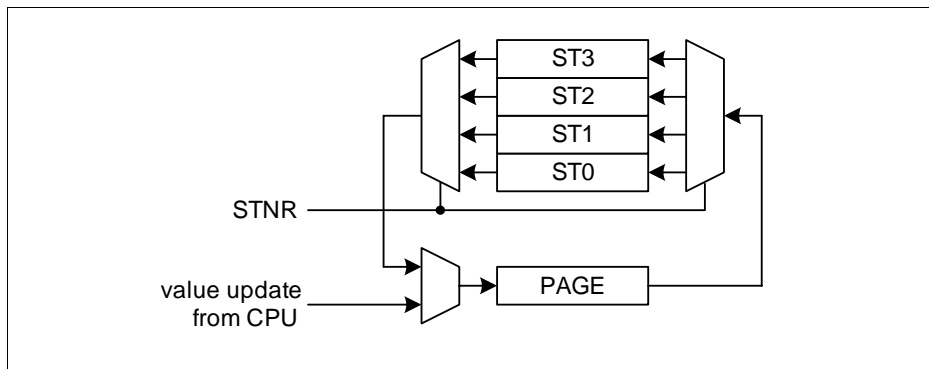


Figure 10 Storage Elements for Paging

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The XC866 supports local address extension for:

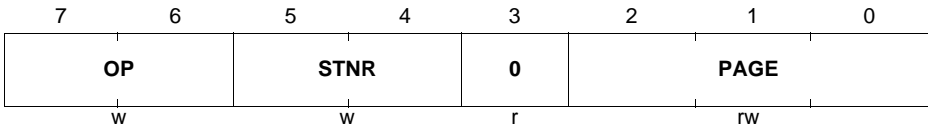
- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers

The page register has the following definition:

MOD_PAGE

Page Register for module MOD

Reset Value: 00_H



Field	Bits	Type	Description
PAGE	[2:0]	rw	<p>Page Bits</p> <p>When written, the value indicates the new page. When read, the value indicates the currently active page.</p>
STNR	[5:4]	w	<p>Storage Number</p> <p>This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10_B, the contents of PAGE are saved in STx before being overwritten with the new value. If OP = 11_B, the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored.</p> <p>00 ST0 is selected. 01 ST1 is selected. 10 ST2 is selected. 11 ST3 is selected.</p>

Field	Bits	Type	Description
OP	[7:6]	w	<p>Operation</p> <p>0X Manual page mode. The value of STNR is ignored and PAGE is directly written.</p> <p>10 New page programming with automatic page saving. The value written to the bit positions of PAGE is stored. In parallel, the previous contents of PAGE are saved in the storage bit field STx indicated by STNR.</p> <p>11 Automatic restore page action. The value written to the bit positions PAGE is ignored and instead, PAGE is overwritten by the contents of the storage bit field STx indicated by STNR.</p>
0	3	r	<p>Reserved</p> <p>Returns 0 if read; should be written with 0.</p>

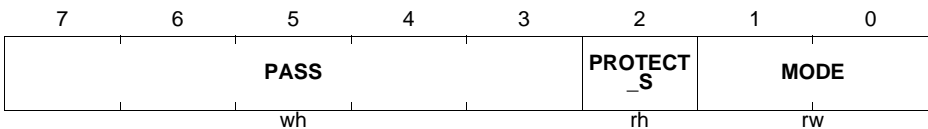
Bit Protection Scheme

The bit protection scheme prevents direct software writing of selected bits (i.e., protected bits) using the PASSWD register. When the bit field MODE is 11_B, writing 10011_B to the bit field PASS opens access to writing of all protected bits, and writing 10101_B to the bit field PASS closes access to writing of all protected bits. Note that access is opened for maximum 32 CCLKs if the “close access” password is not written. If “open access” password is written again before the end of 32 CCLK cycles, there will be a recount of 32 CCLK cycles. The protected bits include NDIV, WD TEN, PD, and SD.

PASSWD

Password Register

Reset Value: 07_H



Field	Bits	Type	Description
MODE	[1:0]	rw	Bit Protection Scheme Control bits 00 Scheme Disabled 11 Scheme Enabled (default) Others: Scheme Enabled These two bits cannot be written directly. To change the value between 11 _B and 00 _B , the bit field PASS must be written with 11000 _B ; only then, will the MODE[1:0] be registered.
PROTECT_S	2	rh	Bit Protection Signal Status bit This bit shows the status of the protection. 0 Software is able to write to all protected bits. 1 Software is unable to write to any protected bits.
PASS	[7:3]	wh	Password bits The Bit Protection Scheme only recognizes three patterns. 11000 _B Enables writing of the bit field MODE. 10011 _B Opens access to writing of all protected bits. 10101 _B Closes access to writing of all protected bits.

XC866 Register Overview

The SFRs of the XC866 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in **Table 3** to **Table 11**, with the addresses of the bitaddressable SFRs appearing in bold typeface.

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Table 3 CPU Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1										
81 _H	SP Stack Pointer Register	Reset: 07 _H	SP							
		Bit Field	rw							
82 _H	DPL Data Pointer Register Low	Reset: 00 _H	DPL7	DPL6	DPL5	DPL4	DPL3	DPL2	DPL1	DPL0
		Bit Field	rw	rw	rw	rw	rw	rw	rw	rw
83 _H	DPH Data Pointer Register High	Reset: 00 _H	DPH7	DPH6	DPH5	DPH4	DPH3	DPH2	DPH1	DPH0
		Bit Field	rw	rw	rw	rw	rw	rw	rw	rw
87 _H	PCON Power Control Register	Reset: 00 _H	SMOD	0			GF1	GF0	0	IDLE
		Bit Field	rw	r			rw	rw	r	rw
88 _H	TCON Timer Control Register	Reset: 00 _H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
		Bit Field	rwh	rw	rwh	rw	rw	rw	rwh	rw
89 _H	TMOD Timer Mode Register	Reset: 00 _H	GATE1	0	T1M		GATE0	0	T0M	
		Bit Field	rw	r	rw		rw	r	rw	
8A _H	TL0 Timer 0 Register Low	Reset: 00 _H	VAL							
		Bit Field	rwh							
8B _H	TL1 Timer 1 Register Low	Reset: 00 _H	VAL							
		Bit Field	rwh							
8C _H	TH0 Timer 0 Register High	Reset: 00 _H	VAL							
		Bit Field	rwh							
8D _H	TH1 Timer 1 Register High	Reset: 00 _H	VAL							
		Bit Field	rwh							
98 _H	SCON Serial Channel Control Register	Reset: 00 _H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Bit Field	rw	rw	rw	rw	rw	rwh	rwh	rwh
99 _H	SBUF Serial Data Buffer Register	Reset: 00 _H	VAL							
		Bit Field	rwh							
A2 _H	EO Extended Operation Register	Reset: 00 _H	0			TRAP_EN	0			DPSEL_0
		Bit Field	r			rw	r			rw
A8 _H	IEN0 Interrupt Enable Register 0	Reset: 00 _H	EA	0	ET2	ES	ET1	EX1	ET0	EX0
		Bit Field	rw	r	rw	rw	rw	rw	rw	rw
B8 _H	IP Interrupt Priority Register	Reset: 00 _H	0		PT2	PS	PT1	PX1	PT0	PX0
		Bit Field	r		rw	rw	rw	rw	rw	rw
B9 _H	IPH Interrupt Priority Register High	Reset: 00 _H	0		PT2H	PSH	PT1H	PX1H	PT0H	PX0H
		Bit Field	r		rw	rw	rw	rw	rw	rw
D0 _H	PSW Program Status Word Register	Reset: 00 _H	CY	AC	F0	RS1	RS0	OV	F1	P
		Bit Field	rw	rwh	rwh	rw	rw	rwh	rwh	rw
E0 _H	ACC Accumulator Register	Reset: 00 _H	ACC7	ACC6	ACC5	ACC4	ACC3	ACC2	ACC1	ACC0
		Bit Field	rw	rw	rw	rw	rw	rw	rw	rw
E8 _H	IEN1 Interrupt Enable Register 1	Reset: 00 _H	ECCIP_3	ECCIP_2	ECCIP_1	ECCIP_0	EXM	EX2	ESSC	EADC
		Bit Field	rw	rw	rw	rw	rw	rw	rw	rw

Table 3 CPU Register Overview (cont'd)

Addr	Register Name	Reset:	Bit	7	6	5	4	3	2	1	0
F0 _H	B B Register	Reset: 00 _H	Bit Field	B7	B6	B5	B4	B3	B2	B1	B0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
F8 _H	IP1 Interrupt Priority Register 1	Reset: 00 _H	Bit Field	PCCIP3	PCCIP2	PCCIP1	PCCIP0	PXM	PX2	PSSC	PADC
			Type	rw	rw	rw	rw	rw	rw	rw	rw
F9 _H	IPH1 Interrupt Priority Register 1 High	Reset: 00 _H	Bit Field	PCCIP3H	PCCIP2H	PCCIP1H	PCCIP0H	PXMH	PX2H	PSSCH	PADCH
			Type	rw	rw	rw	rw	rw	rw	rw	rw

The system control SFRs can be accessed in the standard memory area (RMAP = 0).

Table 4 System Control Register Overview

Addr	Register Name	Reset:	Bit	7	6	5	4	3	2	1	0	
RMAP = 0 or 1												
8F _H	SYSCON0 System Control Register 0	Reset: 00 _H	Bit Field	0							RMAP	
			Type	r							rw	
RMAP = 0												
BF _H	SCU_PAGE Page Register for System Control	Reset: 00 _H	Bit Field	OP		STNR		0	PAGE			
			Type	w		w		r	rw			
RMAP = 0, Page 0												
B3 _H	MODISEL Peripheral Input Select Register	Reset: 00 _H	Bit Field	0		JTAG TDIS	JTAG TCKS	0		EXINT 0IS	URRIS	
			Type	r		rw	rw	r		rw	rw	
B4 _H	IRCON0 Interrupt Request Register 0	Reset: 00 _H	Bit Field	0	EXINT 6	EXINT 5	EXINT 4	EXINT 3	EXINT 2	EXINT 1	EXINT 0	
			Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh	
B5 _H	IRCON1 Interrupt Request Register 1	Reset: 00 _H	Bit Field	0			ADCS RC1	ADCS RC0	RIR	TIR	EIR	
			Type	r			rwh	rwh	rwh	rwh	rwh	
B7 _H	EXICON0 External Interrupt Control Register 0	Reset: 00 _H	Bit Field	EXINT3		EXINT2		EXINT1		EXINT0		
			Type	rw		rw		rw		rw		
BA _H	EXICON1 External Interrupt Control Register 1	Reset: 00 _H	Bit Field	0		EXINT6		EXINT5		EXINT4		
			Type	r		rw		rw		rw		
BB _H	NMICON NMI Control Register	Reset: 00 _H	Bit Field	0	NMI ECC	NMI VDDP	NMI VDD	NMI OCDS	NMI FLASH TIMER	NMI PLL	NMI WDT	
			Type	r	rw	rw	rw	rw	rw	rw	rw	
BC _H	NMISR NMI Status Register	Reset: 00 _H	Bit Field	0	FNMI ECC	FNMI VDDP	FNMI VDD	FNMI OCDS	FNMI FLASH TIMER	FNMI PLL	FNMI WDT	
			Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh	
BD _H	BCON Baud Rate Control Register	Reset: 00 _H	Bit Field	BGSEL		T2EXIS	BREN	BRPRE		R		
			Type	rw		rw	rw	rw		rw		
BE _H	BG Baud Rate Timer/Reload Register	Reset: 00 _H	Bit Field	BR_VALUE								
			Type	rw								
RMAP = 0, Page 1												
B3 _H	ID Identity Register	Reset: 01 _H	Bit Field	PRODID					VERID			
			Type	r					r			
B4 _H	PMCON0 Power Mode Control Register 0	Reset: 00 _H	Bit Field	0	WDT RST	WKRS	WK SEL	SD	PD	WS		
			Type	r	rwh	rwh	rw	rw	rwh	rw		

Table 4 System Control Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
B5 _H	PMCON1 Power Mode Control Register 1 Reset: 00 _H	Bit Field	0				T2_DIS	CCU_DIS	SSC_DIS	ADC_DIS	
		Type	r				rw	rw	rw	rw	
B6 _H	OSC_CON OSC Control Register Reset: 08 _H	Bit Field	0			OSC_PD	XPD	OSC_SS	ORD_RES	OSCR	
		Type	r			rw	rw	rw	rwh	rw	
B7 _H	PLL_CON PLL Control Register Reset: 20 _H	Bit Field	NDIV				VCO_BYP	OSC_DISC	RESLDD	LOCK	
		Type	rw				rw	rw	rwh	rh	
BA _H	CMCON Clock Control Register Reset: 00 _H	Bit Field	0				CLKREL				
		Type	r				rw				
BB _H	PASSWD Password Register Reset: 07 _H	Bit Field	PASS				PROTE_CT_S	MODE			
		Type	wh				rh	rw			
BC _H	FEAL Flash Error Address Register Low Reset: 00 _H	Bit Field	ECCERRADDR[7:0]								
		Type	rh								
BD _H	FEAH Flash Error Address Register High Reset: 00 _H	Bit Field	ECCERRADDR[15:8]								
		Type	rh								

The WDT SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 5 WDT Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP = 1											
BB _H	WDTCON Watchdog Timer Control Register Reset: 00 _H	Bit Field	0		WINB_EN	WDT_PR	0	WDT_EN	WDT_RS	WDT_IN	
		Type	r		rw	rh	r	rw	rwh	rw	
BC _H	WDTREL Watchdog Timer Reload Register Reset: 00 _H	Bit Field	WDTREL								
		Type	rw								
BD _H	WDTWINB Watchdog Window-Boundary Count Register Reset: 00 _H	Bit Field	WDTWINB								
		Type	rw								
BE _H	WDTL Watchdog Timer Register Low Reset: 00 _H	Bit Field	WDT[7:0]								
		Type	rh								
BF _H	WDTH Watchdog Timer Register High Reset: 00 _H	Bit Field	WDT[15:8]								
		Type	rh								

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 6 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
B2 _H	PORT_PAGE Page Register for PORT Reset: 00 _H	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, Page 0										
80 _H	P0_DATA P0 Data Register Reset: 00 _H	Bit Field	0	P5	P4	P3	P2	P1	P0	
		Type	r	rw	rw	rw	rw	rw	rw	
86 _H	P0_DIR P0 Direction Register Reset: 00 _H	Bit Field	0	P5	P4	P3	P2	P1	P0	
		Type	r	rw	rw	rw	rw	rw	rw	

Table 6 Port Register Overview (cont'd)

Addr	Register Name	Reset:	Bit	7	6	5	4	3	2	1	0
90 _H	P1_DATA P1 Data Register	Reset: 00_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
91 _H	P1_DIR P1 Direction Register	Reset: 00_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
A0 _H	P2_DATA P2 Data Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
B0 _H	P3_DATA P3 Data Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
B1 _H	P3_DIR P3 Direction Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 1											
80 _H	P0_PUDSEL P0 Pull-Up/Pull-Down Select Register	Reset: FF_H	Bit Field	0		P5	P4	P3	P2	P1	P0
			Type	r		rw	rw	rw	rw	rw	rw
86 _H	P0_PUDEN P0 Pull-Up/Pull-Down Enable Register	Reset: C4_H	Bit Field	0		P5	P4	P3	P2	P1	P0
			Type	r		rw	rw	rw	rw	rw	rw
90 _H	P1_PUDSEL P1 Pull-Up/Pull-Down Select Register	Reset: FF_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
91 _H	P1_PUDEN P1 Pull-Up/Pull-Down Enable Register	Reset: FF_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
A0 _H	P2_PUDSEL P2 Pull-Up/Pull-Down Select Register	Reset: FF_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
A1 _H	P2_PUDEN P2 Pull-Up/Pull-Down Enable Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
B0 _H	P3_PUDSEL P3 Pull-Up/Pull-Down Select Register	Reset: BF_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
B1 _H	P3_PUDEN P3 Pull-Up/Pull-Down Enable Register	Reset: 40_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 2											
80 _H	P0_ALTSEL0 P0 Alternate Select 0 Register	Reset: 00_H	Bit Field	0		P5	P4	P3	P2	P1	P0
			Type	r		rw	rw	rw	rw	rw	rw
86 _H	P0_ALTSEL1 P0 Alternate Select 1 Register	Reset: 00_H	Bit Field	0		P5	P4	P3	P2	P1	P0
			Type	r		rw	rw	rw	rw	rw	rw
90 _H	P1_ALTSEL0 P1 Alternate Select 0 Register	Reset: 00_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
91 _H	P1_ALTSEL1 P1 Alternate Select 1 Register	Reset: 00_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
B0 _H	P3_ALTSEL0 P3 Alternate Select 0 Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
B1 _H	P3_ALTSEL1 P3 Alternate Select 1 Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 3											
80 _H	P0_OD P0 Open Drain Control Register	Reset: 00_H	Bit Field	0		P5	P4	P3	P2	P1	P0
			Type	r		rw	rw	rw	rw	rw	rw
90 _H	P1_OD P1 Open Drain Control Register	Reset: 00_H	Bit Field	P7	P6	P5	0			P1	P0
			Type	rw	rw	rw	r			rw	rw
B0 _H	P3_OD P3 Open Drain Control Register	Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
			Type	rw	rw	rw	rw	rw	rw	rw	rw

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 7 ADC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP = 0											
D1 _H	ADC_PAGE Page Register for ADC	Reset: 00 _H	Bit Field	OP		STNR		0	PAGE		
			Type	w		w		r	rw		
RMAP = 0, Page 0											
CA _H	ADC_GLOBCTR Global Control Register	Reset: 00 _H	Bit Field	ANON	DW	CTC		0			
			Type	rw	rw	rw		r			
CB _H	ADC_GLOBSTR Global Status Register	Reset: 00 _H	Bit Field	0		CHNR		0	SAM PLE	BUSY	
			Type	r		rh		r	rh	rh	
CC _H	ADC_PRAR Priority and Arbitration Register	Reset: 00 _H	Bit Field	ASEN1	ASEN0	0	ARBM	CSM1	PRI01	CSM0	PRI00
			Type	rw	rw	r	rw	rw	rw	rw	rw
CD _H	ADC_LCBR Limit Check Boundary Register	Reset: B7 _H	Bit Field	BOUND1				BOUND0			
			Type	rw				rw			
CE _H	ADC_INPCR0 Input Class Register 0	Reset: 00 _H	Bit Field	STC							
			Type	rw							
CF _H	ADC_ETRCR External Trigger Control Register	Reset: 00 _H	Bit Field	SYNEN 1	SYNEN 0	ETRSEL1		ETRSEL0			
			Type	rw	rw	rw		rw			
RMAP = 0, Page 1											
CA _H	ADC_CHCTR0 Channel Control Register 0	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
CB _H	ADC_CHCTR1 Channel Control Register 1	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
CC _H	ADC_CHCTR2 Channel Control Register 2	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
CD _H	ADC_CHCTR3 Channel Control Register 3	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
CE _H	ADC_CHCTR4 Channel Control Register 4	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
CF _H	ADC_CHCTR5 Channel Control Register 5	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
D2 _H	ADC_CHCTR6 Channel Control Register 6	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
D3 _H	ADC_CHCTR7 Channel Control Register 7	Reset: 00 _H	Bit Field	0	LCC		0	RESRSEL			
			Type	r	rw		r	rw			
RMAP = 0, Page 2											
CA _H	ADC_RESR0L Result Register 0 Low	Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
			Type	rh		r	rh	rh	rh		
CB _H	ADC_RESR0H Result Register 0 High	Reset: 00 _H	Bit Field	RESULT[9:2]							
			Type	rh							
CC _H	ADC_RESR1L Result Register 1 Low	Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
			Type	rh		r	rh	rh	rh		
CD _H	ADC_RESR1H Result Register 1 High	Reset: 00 _H	Bit Field	RESULT[9:2]							
			Type	rh							
CE _H	ADC_RESR2L Result Register 2 Low	Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
			Type	rh		r	rh	rh	rh		
CF _H	ADC_RESR2H Result Register 2 High	Reset: 00 _H	Bit Field	RESULT[9:2]							
			Type	rh							

Table 7 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
D2 _H	ADC_RESR3L Result Register 3 Low Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR			
		Type	rh		r	rh	rh	rh			
D3 _H	ADC_RESR3H Result Register 3 High Reset: 00 _H	Bit Field	RESULT[9:2]								
		Type	rh								
RMAP = 0, Page 3											
CA _H	ADC_RESRA0L Result Register 0, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]		VF	DRC	CHNR				
		Type	rh		rh	rh	rh				
CB _H	ADC_RESRA0H Result Register 0, View A High Reset: 00 _H	Bit Field	RESULT[10:3]								
		Type	rh								
CC _H	ADC_RESRA1L Result Register 1, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]		VF	DRC	CHNR				
		Type	rh		rh	rh	rh				
CD _H	ADC_RESRA1H Result Register 1, View A High Reset: 00 _H	Bit Field	RESULT[10:3]								
		Type	rh								
CE _H	ADC_RESRA2L Result Register 2, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]		VF	DRC	CHNR				
		Type	rh		rh	rh	rh				
CF _H	ADC_RESRA2H Result Register 2, View A High Reset: 00 _H	Bit Field	RESULT[10:3]								
		Type	rh								
D2 _H	ADC_RESRA3L Result Register 3, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]		VF	DRC	CHNR				
		Type	rh		rh	rh	rh				
D3 _H	ADC_RESRA3H Result Register 3, View A High Reset: 00 _H	Bit Field	RESULT[10:3]								
		Type	rh								
RMAP = 0, Page 4											
CA _H	ADC_RCR0 Result Control Register 0 Reset: 00 _H	Bit Field	VFCTR	WFR	FEN	IEN	0			DRCT R	
		Type	rw	rw	rw	rw	r			rw	
CB _H	ADC_RCR1 Result Control Register 1 Reset: 00 _H	Bit Field	VFCTR	WFR	FEN	IEN	0			DRCT R	
		Type	rw	rw	rw	rw	r			rw	
CC _H	ADC_RCR2 Result Control Register 2 Reset: 00 _H	Bit Field	VFCTR	WFR	FEN	IEN	0			DRCT R	
		Type	rw	rw	rw	rw	r			rw	
CD _H	ADC_RCR3 Result Control Register 3 Reset: 00 _H	Bit Field	VFCTR	WFR	FEN	IEN	0			DRCT R	
		Type	rw	rw	rw	rw	r			rw	
CE _H	ADC_VFCR Valid Flag Clear Register Reset: 00 _H	Bit Field	0				VFC3	VFC2	VFC1	VFC0	
		Type	r				w	w	w	w	
RMAP = 0, Page 5											
CA _H	ADC_CHINFR Channel Interrupt Flag Register Reset: 00 _H	Bit Field	CHINF 7	CHINF 6	CHINF 5	CHINF 4	CHINF 3	CHINF 2	CHINF 1	CHINF 0	
		Type	rh	rh	rh	rh	rh	rh	rh	rh	rh
CB _H	ADC_CHINCR Channel Interrupt Clear Register Reset: 00 _H	Bit Field	CHINC 7	CHINC 6	CHINC 5	CHINC 4	CHINC 3	CHINC 2	CHINC 1	CHINC 0	
		Type	w	w	w	w	w	w	w	w	w
CC _H	ADC_CHINSR Channel Interrupt Set Register Reset: 00 _H	Bit Field	CHINS 7	CHINS 6	CHINS 5	CHINS 4	CHINS 3	CHINS 2	CHINS 1	CHINS 0	
		Type	w	w	w	w	w	w	w	w	w
CD _H	ADC_CHINPR Channel Interrupt Node Pointer Register Reset: 00 _H	Bit Field	CHINP 7	CHINP 6	CHINP 5	CHINP 4	CHINP 3	CHINP 2	CHINP 1	CHINP 0	
		Type	rw	rw	rw	rw	rw	rw	rw	rw	rw
CE _H	ADC_EVINFR Event Interrupt Flag Register Reset: 00 _H	Bit Field	EVINF 7	EVINF 6	EVINF 5	EVINF 4	0			EVINF 1	EVINF 0
		Type	rh	rh	rh	rh	r			rh	rh

Table 7 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CF _H	ADC_EVINCR Event Interrupt Clear Flag Register Reset: 00 _H	Bit Field	EVINC 7	EVINC 6	EVINC 5	EVINC 4	0		EVINC 1	EVINC 0
		Type	w	w	w	w	r		w	w
D2 _H	ADC_EVINSR Event Interrupt Set Flag Register Reset: 00 _H	Bit Field	EVINS 7	EVINS 6	EVINS 5	EVINS 4	0		EVINS 1	EVINS 0
		Type	w	w	w	w	r		w	w
D3 _H	ADC_EVINPR Event Interrupt Node Pointer Register Reset: 00 _H	Bit Field	EVINP 7	EVINP 6	EVINP 5	EVINP 4	0		EVINP 1	EVINP 0
		Type	rw	rw	rw	rw	r		rw	rw
RMAP = 0, Page 6										
CA _H	ADC_CRCR1 Conversion Request Control Register 1 Reset: 00 _H	Bit Field	CH7	CH6	CH5	CH4	0			
		Type	rw	rw	rw	rw	r			
CB _H	ADC_CRPR1 Conversion Request Pending Register 1 Reset: 00 _H	Bit Field	CHP7	CHP6	CHP5	CHP4	0			
		Type	rw	rw	rw	rw	r			
CC _H	ADC_CRMR1 Conversion Request Mode Register 1 Reset: 00 _H	Bit Field	0	LDEV	CLR PND	SCAN	ENSI	ENTR	ENGT	
		Type	r	w	w	rw	rw	rw	rw	
CD _H	ADC_QMR0 Queue Mode Register 0 Reset: 00 _H	Bit Field	CEV	TREV	FLUSH	CLR V	TRMD	ENTR	ENGT	
		Type	w	w	w	w	rw	rw	rw	
CE _H	ADC_QSR0 Queue Status Register 0 Reset: 20 _H	Bit Field	0		EMPTY	EV	0			
		Type	r		rh	rh	r			
CF _H	ADC_Q0R0 Queue 0 Register 0 Reset: 00 _H	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
D2 _H	ADC_QBUR0 Queue Backup Register 0 Reset: 00 _H	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
D2 _H	ADC_QINR0 Queue Input Register 0 Reset: 00 _H	Bit Field	EXTR	ENSI	RF	0		REQCHNR		
		Type	w	w	w	r		w		

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 8 Timer 2 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
C0 _H	T2_T2CON Timer 2 Control Register Reset: 00 _H	Bit Field	TF2	EXF2	0		EXEN2	TR2	C/T2	CP/ RL2
		Type	rw	rw	r		rw	rw	rw	rw
C1 _H	T2_T2MOD Timer 2 Mode Register Reset: 00 _H	Bit Field	0		EDGE SEL	PREN	T2PRE		DCEN	
		Type	r		rw	rw	rw		rw	
C2 _H	T2_RC2L Timer 2 Reload/Capture Register Low Reset: 00 _H	Bit Field	RC2[7:0]							
		Type	rw							
C3 _H	T2_RC2H Timer 2 Reload/Capture Register High Reset: 00 _H	Bit Field	RC2[15:8]							
		Type	rw							
C4 _H	T2_T2L Timer 2 Register Low Reset: 00 _H	Bit Field	THL2[7:0]							
		Type	rw							
C5 _H	T2_T2H Timer 2 Register High Reset: 00 _H	Bit Field	THL2[15:8]							
		Type	rw							

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 9 CCU6 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP = 0											
A3 _H	CCU6_PAGE Page Register for CCU6	Reset: 00 _H	Bit Field		OP		STNR		0		PAGE
			Type		w		w		r		rw
RMAP = 0, Page 0											
9A _H	CCU6_CC63SRL Capture/Compare Shadow Register for Channel CC63 Low	Reset: 00 _H	Bit Field		CC63SL						
			Type		rw						
9B _H	CCU6_CC63SRH Capture/Compare Shadow Register for Channel CC63 High	Reset: 00 _H	Bit Field		CC63SH						
			Type		rw						
9C _H	CCU6_TCTR4L Timer Control Register 4 Low	Reset: 00 _H	Bit Field	T12 STD	T12 STR	0		DTRES	T12 RES	T12RS	T12RR
			Type	w	w	r		w	w	w	w
9D _H	CCU6_TCTR4H Timer Control Register 4 High	Reset: 00 _H	Bit Field	T13 STD	T13 STR	0			T13 RES	T13RS	T13RR
			Type	w	w	r			w	w	w
9E _H	CCU6_MCMOUTSL Multi-Channel Mode Output Shadow Register Low	Reset: 00 _H	Bit Field	STRM CM	0	MCMPMS					
			Type	w	r	rw					
9F _H	CCU6_MCMOUTSH Multi-Channel Mode Output Shadow Register High	Reset: 00 _H	Bit Field	STRHP	0	CURHS			EXPHS		
			Type	w	r	rw			rw		
A4 _H	CCU6_ISR Capture/Compare Interrupt Status Reset Register Low	Reset: 00 _H	Bit Field	RT12P M	RT12O M	RCC62 F	RCC62 R	RCC61 F	RCC61 R	RCC60 F	RCC60 R
			Type	w	w	w	w	w	w	w	w
A5 _H	CCU6_ISRH Capture/Compare Interrupt Status Reset Register High	Reset: 00 _H	Bit Field	RSTR	RIDL	RWHE	RCHE	0	RTRPF	RT13 PM	RT13 CM
			Type	w	w	w	w	r	w	w	w
A6 _H	CCU6_CMPMODIFL Compare State Modification Register Low	Reset: 00 _H	Bit Field	0	MCC63 S	0			MCC62 S	MCC61 S	MCC60 S
			Type	r	w	r			w	w	w
A7 _H	CCU6_CMPMODIFH Compare State Modification Register High	Reset: 00 _H	Bit Field	0	MCC63 R	0			MCC62 R	MCC61 R	MCC60 R
			Type	r	w	r			w	w	w
FA _H	CCU6_CC60SRL Capture/Compare Shadow Register for Channel CC60 Low	Reset: 00 _H	Bit Field		CC60SL						
			Type		rwh						
FB _H	CCU6_CC60SRH Capture/Compare Shadow Register for Channel CC60 High	Reset: 00 _H	Bit Field		CC60SH						
			Type		rwh						
FC _H	CCU6_CC61SRL Capture/Compare Shadow Register for Channel CC61 Low	Reset: 00 _H	Bit Field		CC61SL						
			Type		rwh						
FD _H	CCU6_CC61SRH Capture/Compare Shadow Register for Channel CC61 High	Reset: 00 _H	Bit Field		CC61SH						
			Type		rwh						
FE _H	CCU6_CC62SRL Capture/Compare Shadow Register for Channel CC62 Low	Reset: 00 _H	Bit Field		CC62SL						
			Type		rwh						
FF _H	CCU6_CC62SRH Capture/Compare Shadow Register for Channel CC62 High	Reset: 00 _H	Bit Field		CC62SH						
			Type		rwh						

Table 9 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0, Page 1										
9A _H	CCU6_CC63RL Capture/Compare Register for Channel CC63 Low Reset: 00_H	Bit Field	CC63VL							
		Type	rh							
9B _H	CCU6_CC63RH Capture/Compare Register for Channel CC63 High Reset: 00_H	Bit Field	CC63VH							
		Type	rh							
9C _H	CCU6_T12PRL Timer T12 Period Register Low Reset: 00_H	Bit Field	T12PVL							
		Type	rwh							
9D _H	CCU6_T12PRH Timer T12 Period Register High Reset: 00_H	Bit Field	T12PVH							
		Type	rwh							
9E _H	CCU6_T13PRL Timer T13 Period Register Low Reset: 00_H	Bit Field	T13PVL							
		Type	rwh							
9F _H	CCU6_T13PRH Timer T13 Period Register High Reset: 00_H	Bit Field	T13PVH							
		Type	rwh							
A4 _H	CCU6_T12DTCL Dead-Time Control Register for Timer T12 Low Reset: 00_H	Bit Field	DTM							
		Type	rw							
A5 _H	CCU6_T12DTCH Dead-Time Control Register for Timer T12 High Reset: 00_H	Bit Field	0	DTR2	DTR1	DTR0	0	DTE2	DTE1	DTE0
		Type	r	rh	rh	rh	r	rw	rw	rw
A6 _H	CCU6_TCTR0L Timer Control Register 0 Low Reset: 00_H	Bit Field	CTM	CDIR	STE12	T12R	T12 PRE	T12CLK		
		Type	rw	rh	rh	rh	rw	rw		
A7 _H	CCU6_TCTR0H Timer Control Register 0 High Reset: 00_H	Bit Field	0	STE13	T13R	T13 PRE	T13CLK			
		Type	r	rh	rh	rw	rw			
FA _H	CCU6_CC60RL Capture/Compare Register for Channel CC60 Low Reset: 00_H	Bit Field	CC60VL							
		Type	rh							
FB _H	CCU6_CC60RH Capture/Compare Register for Channel CC60 High Reset: 00_H	Bit Field	CC60VH							
		Type	rh							
FC _H	CCU6_CC61RL Capture/Compare Register for Channel CC61 Low Reset: 00_H	Bit Field	CC61VL							
		Type	rh							
FD _H	CCU6_CC61RH Capture/Compare Register for Channel CC61 High Reset: 00_H	Bit Field	CC61VH							
		Type	rh							
FE _H	CCU6_CC62RL Capture/Compare Register for Channel CC62 Low Reset: 00_H	Bit Field	CC62VL							
		Type	rh							
FF _H	CCU6_CC62RH Capture/Compare Register for Channel CC62 High Reset: 00_H	Bit Field	CC62VH							
		Type	rh							
RMAP = 0, Page 2										
9A _H	CCU6_T12MSELL T12 Capture/Compare Mode Select Register Low Reset: 00_H	Bit Field	MSEL61				MSEL60			
		Type	rw				rw			
9B _H	CCU6_T12MSELH T12 Capture/Compare Mode Select Register High Reset: 00_H	Bit Field	DBYP	HSYNC			MSEL62			
		Type	rw	rw			rw			

Table 9 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
9C _H	CCU6_IENL Reset: 00_H Capture/Compare Interrupt Enable Register Low	Bit Field	ENT12 PM	ENT12 OM	ENCC 62F	ENCC 62R	ENCC 61F	ENCC 61R	ENCC 60F	ENCC 60R	
		Type	rw	rw	rw	rw	rw	rw	rw	rw	
9D _H	CCU6_IENH Reset: 00_H Capture/Compare Interrupt Enable Register High	Bit Field	ENSTR	EN IDLE	EN WHE	EN CHE	0	EN TRPF	ENT13 PM	ENT13 CM	
		Type	rw	rw	rw	rw	r	rw	rw	rw	
9E _H	CCU6_INPL Reset: 40_H Capture/Compare Interrupt Node Pointer Register Low	Bit Field	INPCHE		INPCC62		INPCC61		INPCC60		
		Type	rw		rw		rw		rw		
9F _H	CCU6_INPH Reset: 39_H Capture/Compare Interrupt Node Pointer Register High	Bit Field	0		INPT13		INPT12		INPERR		
		Type	r		rw		rw		rw		
A4 _H	CCU6_ISSL Reset: 00_H Capture/Compare Interrupt Status Set Register Low	Bit Field	ST12P M	ST12O M	SCC62 F	SCC62 R	SCC61 F	SCC61 R	SCC60 F	SCC60 R	
		Type	w	w	w	w	w	w	w	w	
A5 _H	CCU6_ISSH Reset: 00_H Capture/Compare Interrupt Status Set Register High	Bit Field	SSTR	SIDLE	SWHE	SCHE	SWHC	STRPF	ST13 PM	ST13 CM	
		Type	w	w	w	w	w	w	w	w	
A6 _H	CCU6_PSLR Reset: 00_H Passive State Level Register	Bit Field	PSL63	0	PSL						
		Type	rwh	r	rwh						
A7 _H	CCU6_MCMCTR Reset: 00_H Multi-Channel Mode Control Register	Bit Field	0		SWSYN		0	SWSEL			
		Type	r		rw		r	rw			
FA _H	CCU6_TCTR2L Reset: 00_H Timer Control Register 2 Low	Bit Field	0	T13TED		T13TEC			T13 SSC	T12 SSC	
		Type	r	rw		rw			rw	rw	
FB _H	CCU6_TCTR2H Reset: 00_H Timer Control Register 2 High	Bit Field	0				T13RSEL		T12RSEL		
		Type	r				rw		rw		
FC _H	CCU6_MODCTRL Reset: 00_H Modulation Control Register Low	Bit Field	MC MEN	0	T12MODEN						
		Type	rw	r	rw						
FD _H	CCU6_MODCTRH Reset: 00_H Modulation Control Register High	Bit Field	ECT13 O	0	T13MODEN						
		Type	rw	r	rw						
FE _H	CCU6_TRPCTRL Reset: 00_H Trap Control Register Low	Bit Field	0					TRPM2	TRPM1	TRPM0	
		Type	r					rw	rw	rw	
FF _H	CCU6_TRPCTRH Reset: 00_H Trap Control Register High	Bit Field	TRPPE N	TRPEN 13	TRPEN						
		Type	rw	rw	rw						
RMAP = 0, Page 3											
9A _H	CCU6_MCMOUTL Reset: 00_H Multi-Channel Mode Output Register Low	Bit Field	0	R	MCMP						
		Type	r	rh	rh						
9B _H	CCU6_MCMOUTH Reset: 00_H Multi-Channel Mode Output Register High	Bit Field	0		CURH			EXPH			
		Type	r		rh			rh			
9C _H	CCU6_ISL Reset: 00_H Capture/Compare Interrupt Status Register Low	Bit Field	T12PM	T12OM	ICC62F	ICC62 R	ICC61F	ICC61 R	ICC60F	ICC60 R	
		Type	rh	rh	rh	rh	rh	rh	rh	rh	
9D _H	CCU6_ISH Reset: 00_H Capture/Compare Interrupt Status Register High	Bit Field	STR	IDLE	WHE	CHE	TRPS	TRPF	T13PM	T13CM	
		Type	rh	rh	rh	rh	rh	rh	rh	rh	
9E _H	CCU6_PISEL0L Reset: 00_H Port Input Select Register 0 Low	Bit Field	ISTRP		ISCC62		ISCC61		ISCC60		
		Type	rw		rw		rw		rw		

Table 9 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
9F _H	CCU6_PISEL0H Reset: 00 _H Port Input Select Register 0 High	Bit Field	IST12HR		ISPOS2		ISPOS1		ISPOS0	
		Type	rw		rw		rw		rw	
A4 _H	CCU6_PISEL2 Reset: 00 _H Port Input Select Register 2	Bit Field	0						IST13HR	
		Type	r						rw	
FA _H	CCU6_T12L Reset: 00 _H Timer T12 Counter Register Low	Bit Field	T12CVL							
		Type	rwh							
FB _H	CCU6_T12H Reset: 00 _H Timer T12 Counter Register High	Bit Field	T12CVH							
		Type	rwh							
FC _H	CCU6_T13L Reset: 00 _H Timer T13 Counter Register Low	Bit Field	T13CVL							
		Type	rwh							
FD _H	CCU6_T13H Reset: 00 _H Timer T13 Counter Register High	Bit Field	T13CVH							
		Type	rwh							
FE _H	CCU6_CMPSTATL Reset: 00 _H Compare State Register Low	Bit Field	0	CC63 ST	CCPO S2	CCPO S1	CCPO S0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF _H	CCU6_CMPSTATH Reset: 00 _H Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 SSC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
RMAP = 0											
A9 _H	SSC_PISEL Reset: 00 _H Port Input Select Register	Bit Field	0						CIS	SIS	MIS
		Type	r						rw	rw	rw
AA _H	SSC_CONL Reset: 00 _H Control Register Low <i>Programming Mode</i>	Bit Field	LB	PO	PH	HB	BM				
		Type	rw	rw	rh	rw	rw				
	<i>Operating Mode</i>	Bit Field	0						BC		
		Type	r						rh		
AB _H	SSC_CONH Reset: 00 _H Control Register High <i>Programming Mode</i>	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN	
		Type	rw	rw	r	rw	rw	rw	rw	rw	
	<i>Operating Mode</i>	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE	
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh	
AC _H	SSC_TBL Reset: 00 _H Transmitter Buffer Register Low	Bit Field	TB_VALUE								
		Type	rw								
AD _H	SSC_RBL Reset: 00 _H Receiver Buffer Register Low	Bit Field	RB_VALUE								
		Type	rh								
AE _H	SSC_BRL Reset: 00 _H Baudrate Timer Reload Register Low	Bit Field	BR_VALUE[7:0]								
		Type	rw								
AF _H	SSC_BRH Reset: 00 _H Baudrate Timer Reload Register High	Bit Field	BR_VALUE[15:8]								
		Type	rw								

The OCDS SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 11 OCDS Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0		
RMAP = 1												
E9 _H	MMCR2 Monitor Mode Control Register 2 Reset: 00_H	Bit Field	EXBC_P	EXBC	MBCO_N_P	MBCO_N	MMEP_P	MMEP	MMOD_E	JENA		
		Type	w	rw	w	rwh	w	rwh	rh	rh		
F1 _H	MMCR Monitor Mode Control Register Reset: 00_H	Bit Field	MEXIT_P	MEXIT	MSTEP_P	MSTEP	MRAM_S_P	MRAM_S	TRF	RRF		
		Type	w	hw	w	rw	w	rwh	rh	rh		
F2 _H	MMSR Monitor Mode Status Register Reset: 00_H	Bit Field	MBCA_M	MBCIN	EXBF	SWBF	HWB3_F	HWB2_F	HWB1_F	HWB0_F		
		Type	rw	rh	rwh	rwh	rwh	rwh	rwh	rwh		
F3 _H	MMBPCR BreakPoints Control Register Reset: 00_H	Bit Field	SWBC	HWB3C		HWB2C		HWB1_C	HWB0C			
		Type	rw	rw		rw		rw	rw			
F4 _H	MMICR Monitor Mode Interrupt Control Register Reset: 00_H	Bit Field	DVECT	DRETR	0		MMUIE_P	MMUIE	RRIE_P	RRIE		
		Type	rwh	rwh	r		w	rw	w	rw		
F5 _H	MMDR Monitor Mode Data Register Reset: 00_H <i>Receive</i>	Bit Field	MMRR									
		Type	rh									
		<i>Transmit</i>	Bit Field	MMTR								
			Type	w								
F6 _H	HWBPSR Hardware Breakpoints Select Register Reset: 00_H	Bit Field	0			BPSEL_P	BPSEL					
		Type	r			w	rw					
F7 _H	HWBPDR Hardware Breakpoints Data Register Reset: 00_H	Bit Field	HWBPxx									
		Type	rw									

Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features:

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- 32-byte minimum program width¹⁾
- 1-sector minimum erase width
- 1-byte read access
- 112.5 ns minimum read access time ($3 \times t_{\text{CCLK}} @ f_{\text{CCLK}} = 26.7 \text{ MHz}^2)$)
- Operating supply voltage: $2.5 \text{ V} \pm 7.5 \%$
- Program time: 2.2 ms (typical)
- Erase time: 120 ms (typical)

Table 12 Flash Data Retention and Endurance Targets

Retention up to ¹⁾	Endurance up to ¹⁾	Programming Temperature	Size
20 years	1,000 cycles	0 – 100°C	15 Kbytes
5 years	10,000 cycles	-40 – 125°C	896 bytes
2 years	100,000 cycles	-40 – 125°C	128 bytes

¹⁾ Specification according to operating temperature profile with 0.2ppm error rate.

¹⁾ P-Flash: 32-byte wordline can only be programmed once, i.e., one gate disturb allowed.

D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

²⁾ $f_{\text{sys}} = 80 \text{ MHz}$ ($f_{\text{CCLK}} = 26.7 \text{ MHz}$) is the maximum allowable frequency for Flash read access.

$f_{\text{sys}} = 80 \text{ MHz}$ is also the only frequency for Flash programming and erasing.

Flash Bank Sectorization

The XC866 product family offers four Flash devices with either 8 Kbytes or 16 Kbytes of embedded Flash memory. These Flash memory sizes are made up of two or four 4-Kbyte Flash banks, respectively. Each Flash device consists of Program Flash (P-Flash) bank(s) and a single Data Flash (D-Flash) bank with different sectorization shown in **Figure 11**. Both types can be used for code and data storage. The label “Data” neither implies that the D-Flash is mapped to the data memory region, nor that it can only be used for data storage. It is used to distinguish the different Flash bank sectorizations. The XC866 ROM devices offer a single 4-Kbyte D-Flash bank.

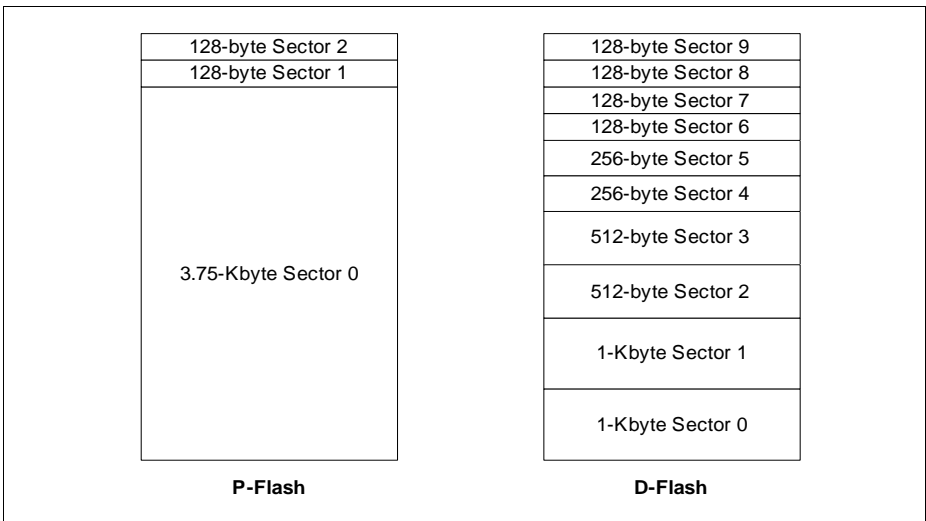


Figure 11 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. Hence, it is possible to program the same WL, for example, with 16 bytes of data in two times (see [Figure 12](#)).

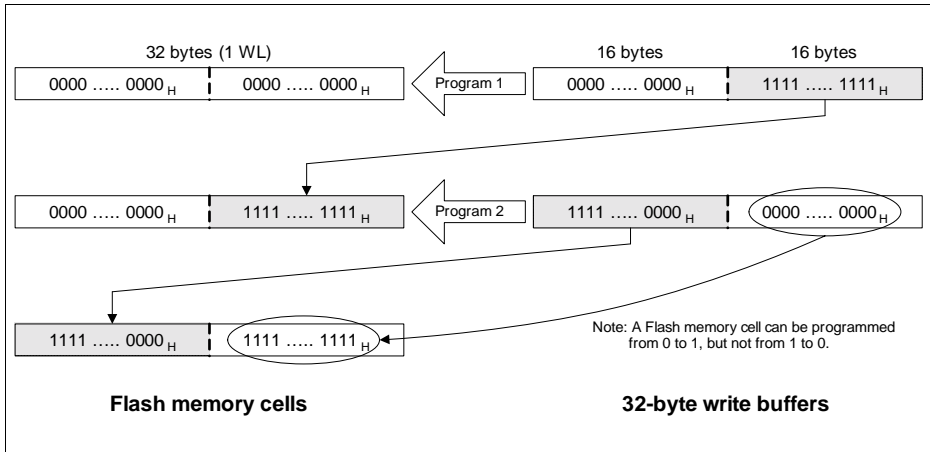


Figure 12 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent “over-programming”.

Interrupt System

The XC800 Core supports one non-maskable interrupt (NMI) and 14 maskable interrupt requests. In addition to the standard interrupt functions supported by the core, e.g., configurable interrupt priority and interrupt masking, the XC866 interrupt system provides extended interrupt support capabilities such as the mapping of each interrupt vector to several interrupt sources to increase the number of interrupt sources supported, and additional status registers for detecting and determining the interrupt source.

Figure 13 to Figure 17 give a general overview of the interrupt sources and illustrates the request and control flags.

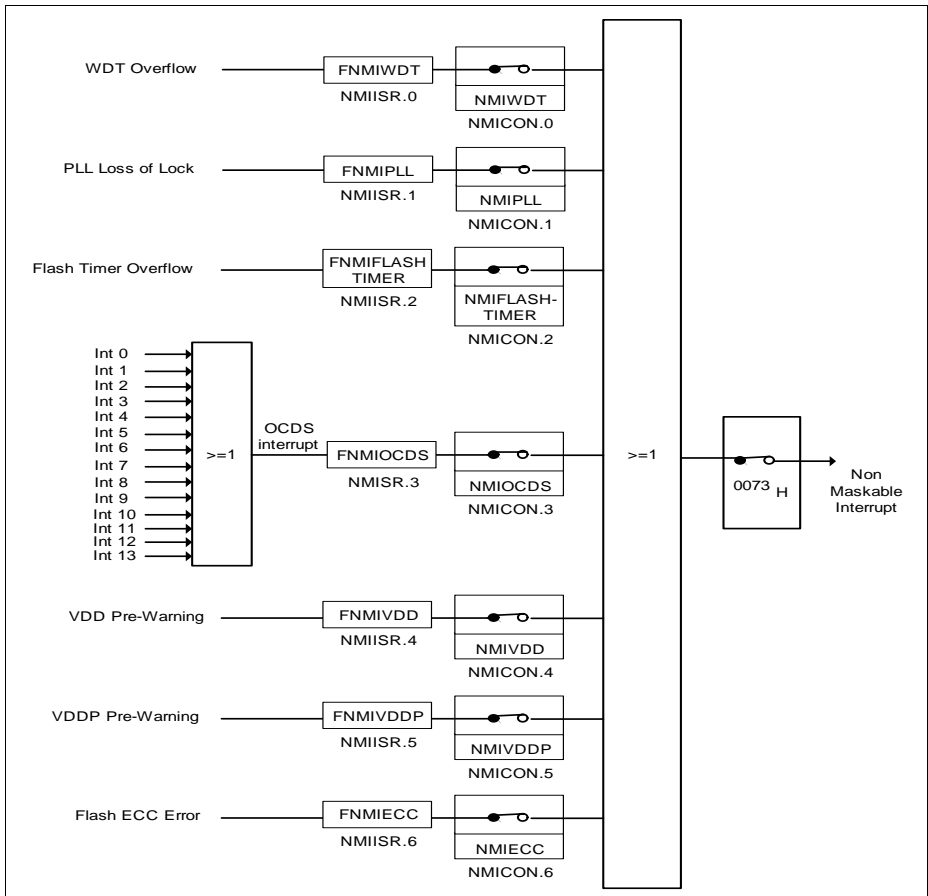


Figure 13 Non-Maskable Interrupt Request Source

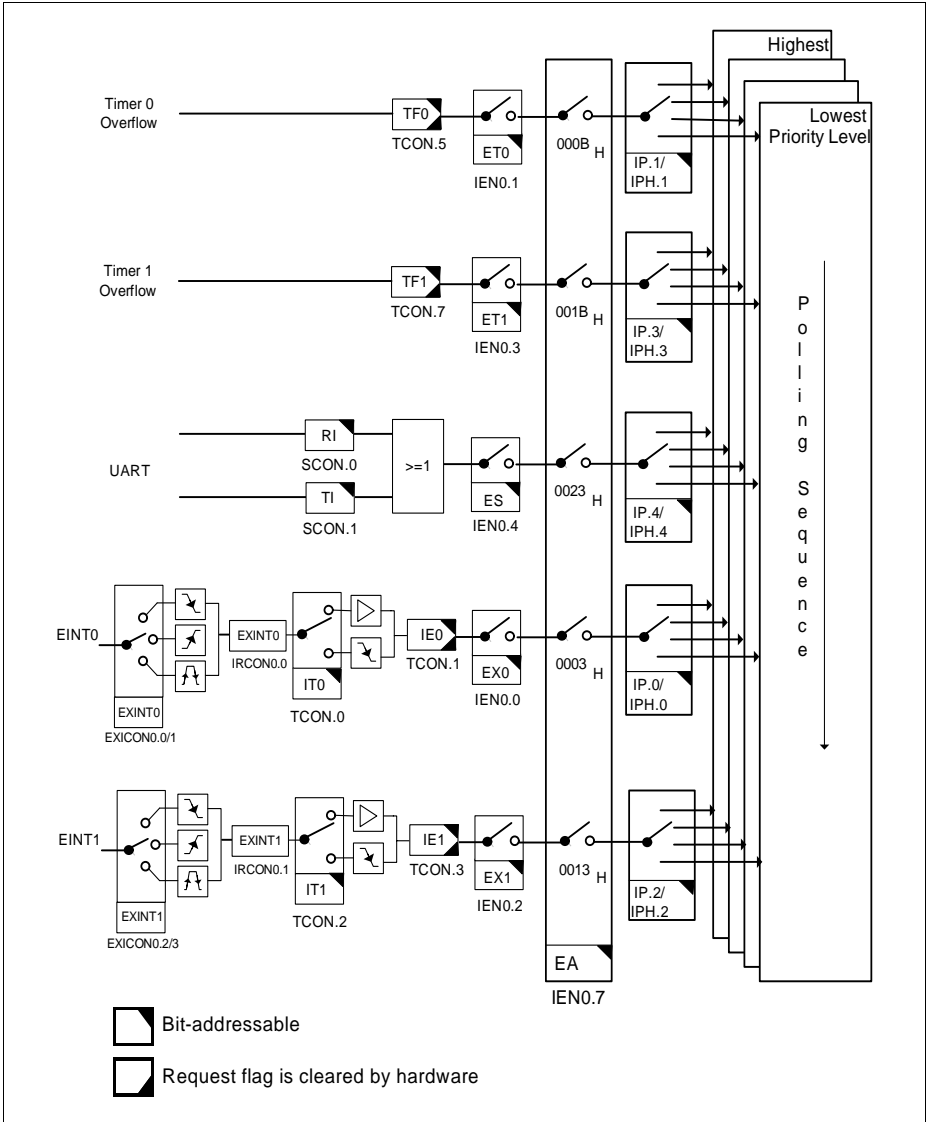


Figure 14 Interrupt Request Sources (Part 1)

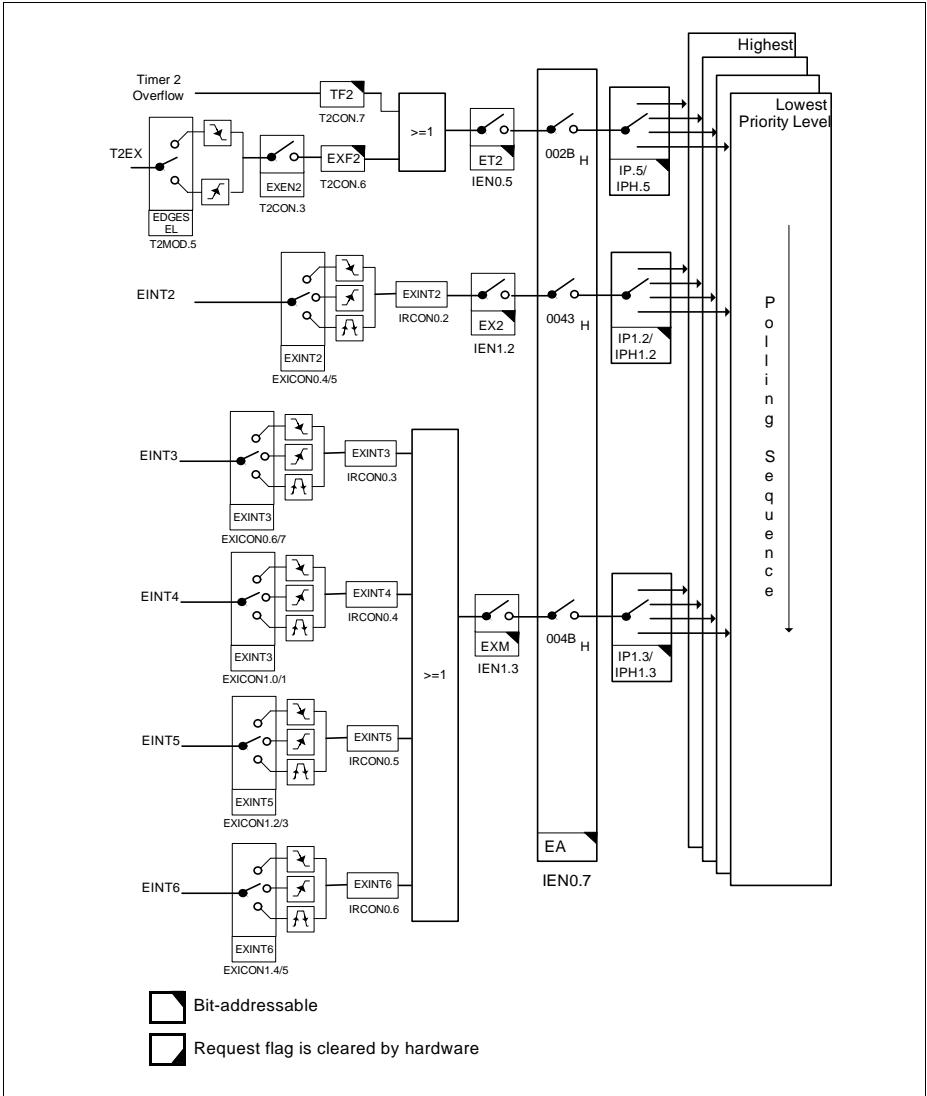


Figure 15 Interrupt Request Sources (Part 2)

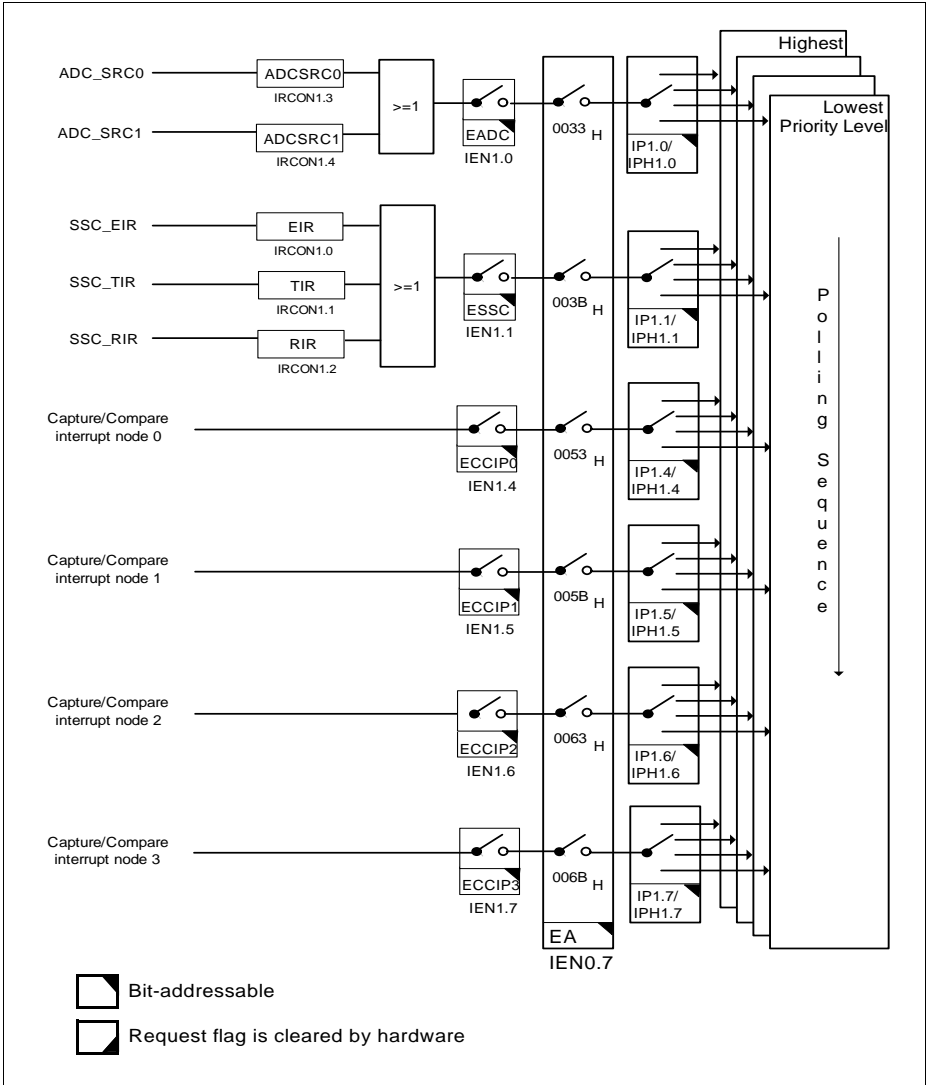


Figure 16 Interrupt Request Sources (Part 3)

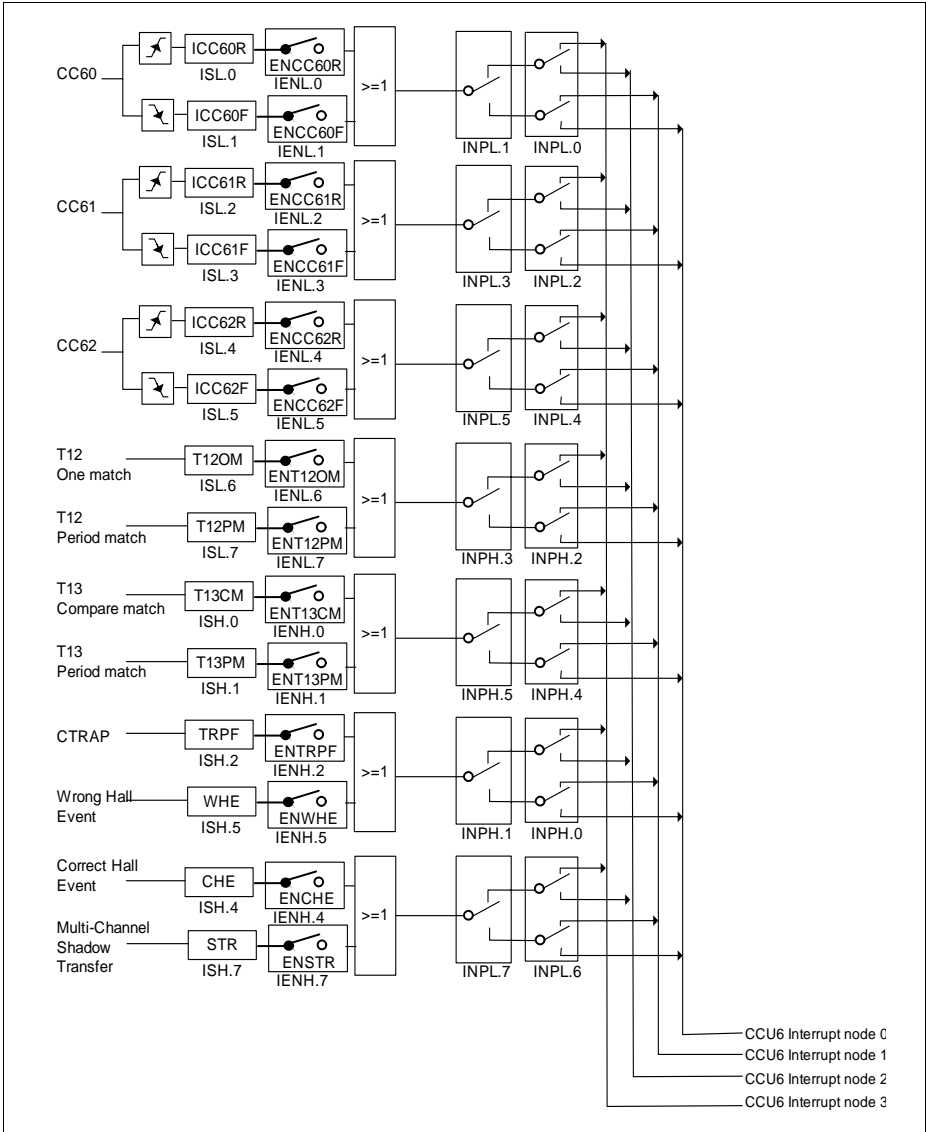


Figure 17 Interrupt Request Sources (Part 4)

Each interrupt input has an associated interrupt vector address. This vector is accessed in order to service the corresponding interrupt source. The assignment of the XC866 interrupt sources is summarized in **Table 13**.

Table 13 Interrupt Vector Addresses

Interrupt Input	Vector Address	Interrupt Sources
NMI	0073 _H	Watchdog Timer, PLL, Flash Interface Timer, OCDS, VDD and VDDP prewarning, Flash ECC
XINTR0	0003 _H	External Interrupt 0
XINTR1	000B _H	Timer 0
XINTR2	0013 _H	External Interrupt 1
XINTR3	001B _H	Timer 1
XINTR4	0023 _H	UART
XINTR5	002B _H	Timer 2
XINTR6	0033 _H	ADC_SRC[1:0]
XINTR7	003B _H	SSC
XINTR8	0043 _H	External Interrupt 2
XINTR9	004B _H	External Interrupt [6:3]
XINTR10	0053 _H	CCU6 INP0
XINTR11	005B _H	CCU6 INP1
XINTR12	0063 _H	CCU6 INP2
XINTR13	006B _H	CCU6 INP3

Each interrupt source, except for NMI, can be individually programmed to one of the four possible priority levels. The NMI has the highest priority and supersedes all other interrupts. Two pairs of interrupt priority registers (IP and IPH, IP1 and IPH1) are available to program the priority level of each non-NMI interrupt vector.

A low-priority interrupt can be interrupted by a high-priority interrupt, but not by another interrupt of the same or lower priority. Further, an interrupt of the highest priority cannot be interrupted by any other interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority are received simultaneously, then an internal polling sequence determines which request is serviced first. Thus, within each priority level, there is a second priority structure determined by the polling sequence shown in [Table 14](#).

Table 14 Priority Structure within Interrupt Level

Source	Level
Non-Maskable Interrupt (NMI)	(highest)
External Interrupt 0	1
Timer 0 Interrupt	2
External Interrupt 1	3
Timer 1 Interrupt	4
UART Interrupt	5
Timer 2 Interrupt	6
ADC Interrupt	7
SSC Interrupt	8
External Interrupt 2	9
External Interrupt [6:3]	10
CCU6 Interrupt Node Pointer 0	11
CCU6 Interrupt Node Pointer 1	12
CCU6 Interrupt Node Pointer 2	13
CCU6 Interrupt Node Pointer 3	14

Parallel Ports

The XC866 has 27 port pins organized into four parallel ports, Port 0 (P0) to Port 3 (P3). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1 and P3 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features:

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features:

- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

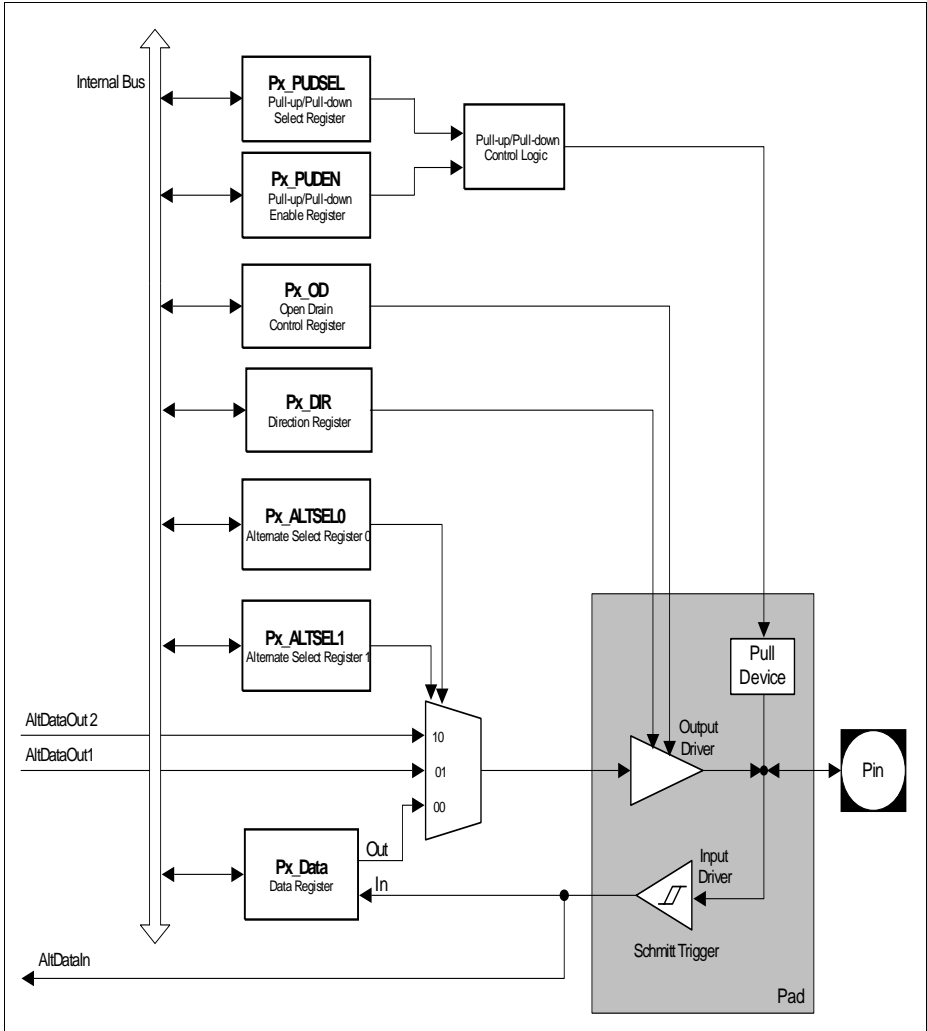


Figure 18 General Structure of Bidirectional Port

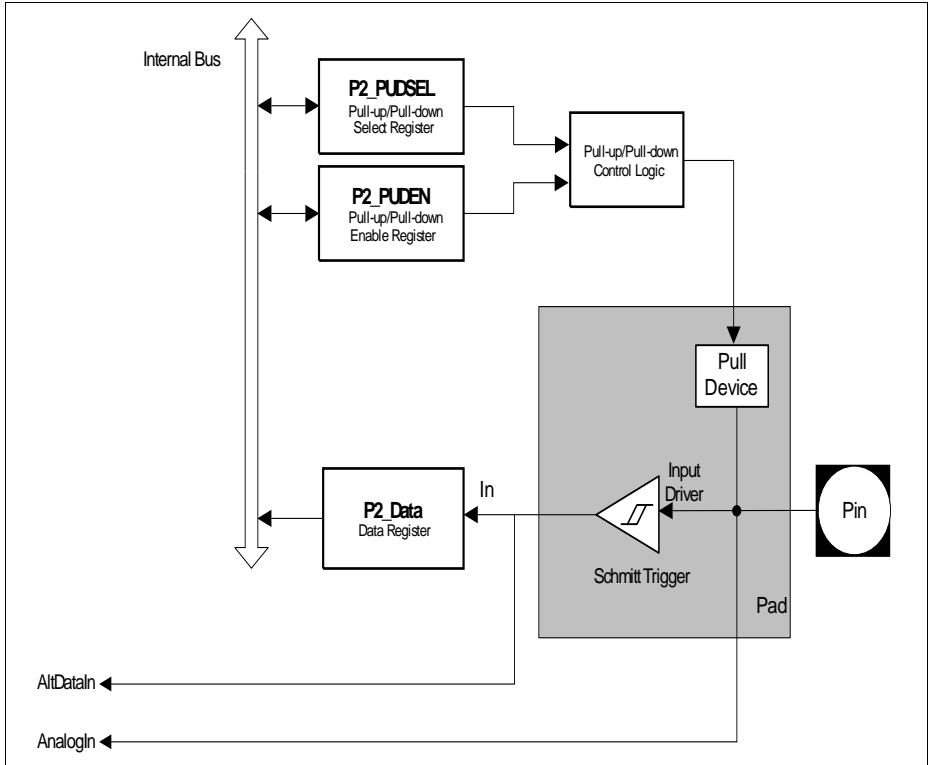


Figure 19 General Structure of Input Port

Power Supply System with Embedded Voltage Regulator

The XC866 microcontroller requires two different levels of power supply:

- 3.3 V or 5.0 V for the Embedded Voltage Regulator (EVR) and Ports
- 2.5 V for the core, memory, on-chip oscillator, and peripherals

Figure 20 shows the XC866 power supply system. A power supply of 3.3 V or 5.0 V must be provided from the external power supply pin. The 2.5 V power supply for the logic is generated by the EVR. The EVR helps to reduce the power consumption of the whole chip and the complexity of the application board design.

The EVR consists of a main voltage regulator and a low power voltage regulator. In active mode, both voltage regulators are enabled. In power-down mode, the main voltage regulator is switched off, while the low power voltage regulator continues to function and provide power supply to the system with low power consumption.

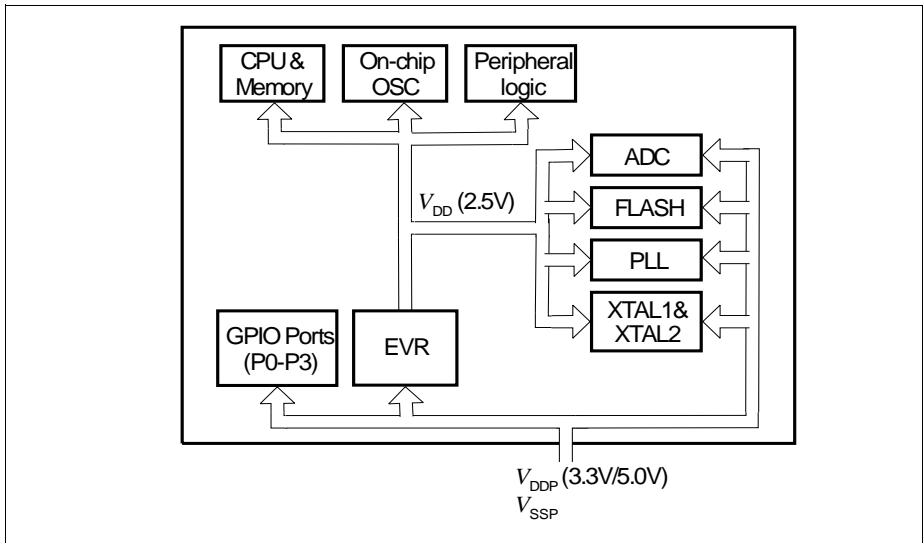


Figure 20 XC866 Power Supply System

EVR Features:

- Input voltage (V_{DDP}): 3.3 V/5.0 V
- Output voltage (V_{DD}): 2.5 V \pm 7.5%
- Low power voltage regulator provided in power-down mode
- V_{DD} and V_{DDP} prewarning detection
- V_{DD} brownout detection

Reset Control

The XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC866 is first powered up, the status of certain pins (see [Table 17](#)) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

The hardware reset function can be used during normal operation or when the chip is in power-down mode. A reset input pin $\overline{\text{RESET}}$ is provided for the hardware reset.

The Watchdog Timer (WDT) module is also capable of resetting the device if it detects a malfunction in the system.

Another type of reset that needs to be detected is a reset while the device is in power-down mode (wake-up reset). While the contents of the static RAM are undefined after a power-on reset, they are well defined after a wake-up reset from power-down mode.

The threshold voltages for power-on reset and brownout reset are shown in [Figure 21](#) and [Table 15](#).

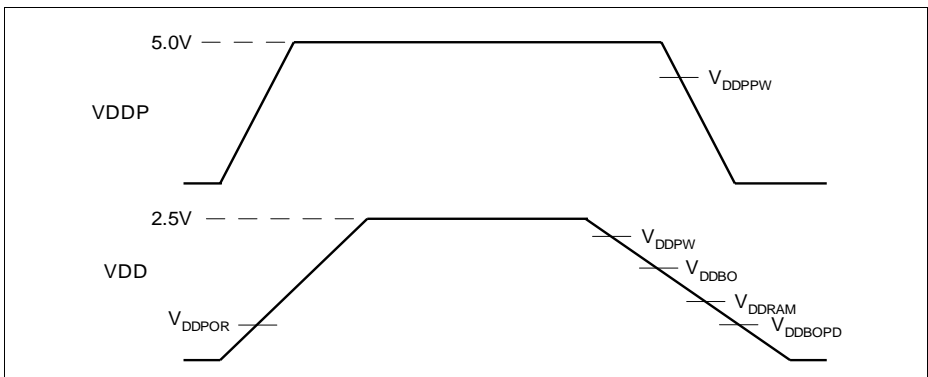


Figure 21 XC866 Supply Threshold Detection

Table 15 XC866 Supply Threshold Detection

Parameters	Symbol	Value	Unit
V_{DD} prewarning voltage ¹⁾	V_{DDPW}	2.3	V
V_{DD} brownout voltage ¹⁾	V_{DDBO}	2.1	V
min. RAM retention voltage	V_{DDRAM}	tbd	V
V_{DD} brownout voltage in power-down ²⁾	V_{DDBOPD}	1.6	V
V_{DDP} prewarning voltage ³⁾	V_{DDPPW}	4.0	V
Power-on reset voltage ²⁾	V_{DDPOR}	1.6	V

1) Detection must be disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V, even in power-down mode.
Detection must be disabled for external power supply of 3.3V.

Module Reset Behavior

Table 16 shows how the functions of the XC866 are affected by the various reset types. A “■” means that this function is reset to its default state.

Table 16 Effect of Reset on Device Functions

Module/ Function	Wake-Up Reset	Watchdog Reset	Hardware Reset	Power-On Reset	Brownout Reset
CPU Core	■	■	■	■	■
Peripherals	■	■	■	■	■
On-Chip Static RAM	Not affected, reliable	Not affected, reliable	Not affected, reliable	Affected, un- reliable	Affected, un- reliable
Oscillator, PLL	■	Not affected	■	■	■
Port Pins	■	■	■	■	■
EVR	The voltage regulator is switched on	Not affected	■	■	■
FLASH	■	■	■	■	■
NMI	■	Disabled	Disabled	■	■

Booting Scheme

When the XC866 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. **Table 17** shows the available boot options in the XC866.

Table 17 XC866 Boot Selection

MBC	TMS	P0.0	Type of Mode	PC Start Value
1	x	x	User Mode; OSC/PLL non-bypassed	0000 _H
0	0	x	BSL Mode; OSC/PLL non-bypassed	0000 _H
0	1	0	OCDS Mode; OSC/PLL non-bypassed	0000 _H

Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the XC866. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features:

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL. In the XC866, the oscillator can be from either of these two sources: the on-chip oscillator (10 MHz) or the external oscillator (3 MHz to 12 MHz). The term “oscillator” is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default. The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.

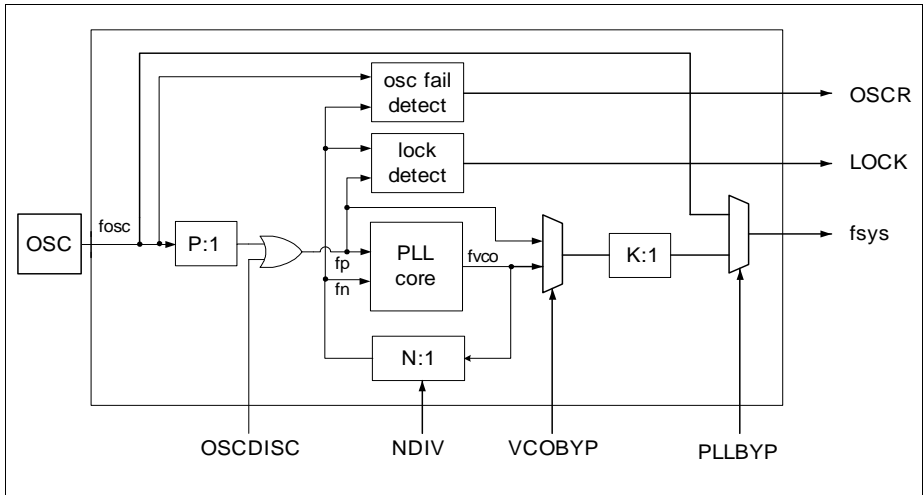


Figure 22 CGU Block Diagram

Direct Drive (PLL Bypass Operation)

During PLL bypass operation, the system clock has the same frequency as the external clock source. For the XC866, the PLL bypass cannot be set active. Hence, the direct drive mode is not available for use.

$$f_{SYS} = f_{OSC}$$

PLL Base Mode

The system clock is derived from the VCO base frequency clock divided by the K factor. Both VCO bypass and PLL bypass must be inactive for this PLL mode.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

PLL Mode

The system clock is derived from the oscillator clock, multiplied by the N factor, and divided by the P and K factors. Both VCO bypass and PLL bypass must be inactive for this PLL mode. The PLL mode is used during normal system operation. .

$$f_{SYS} = f_{OSC} \times \frac{N}{P \times K}$$

System Frequency Selection

For the XC866, the values of P and K are fixed to “1” and “2”, respectively. In order to obtain the required system frequency, f_{SYS} , the value of N can be selected by bit NDIV for different oscillator inputs. **Table 18** provides examples on how $f_{SYS} = 80$ MHz can be obtained for the different oscillator sources.

Table 18 System frequency ($f_{SYS} = 80$ MHz)

Oscillator	fosc	N	P	K	fsys
On-chip	10 MHz	16	1	2	80 MHz
External	10 MHz	16	1	2	80 MHz
	8 MHz	20	1	2	80 MHz
	5 MHz	32	1	2	80 MHz

Note: The XC866 system frequency must be maintained between 75 MHz to 80 MHz.

Table 19 shows the VCO range for the XC866.

Table 19 VCO Range

	min.	max.	Unit
f_{VCO}	150	200	MHz
$f_{VCOFREE}$	40	130	MHz

Resonator Circuitry

Figure 23 shows the recommended ceramic resonator circuitry.

When using an external resonator, its frequency can be within the range of 3 MHz to 12 MHz. A resonator load circuitry must be used, connected to both pins, XTAL1 and XTAL2. It normally consists of two load capacitances C_1 and C_2 , and in some cases, a feedback (R_f) and/or damp (R_d) resistor might be necessary.

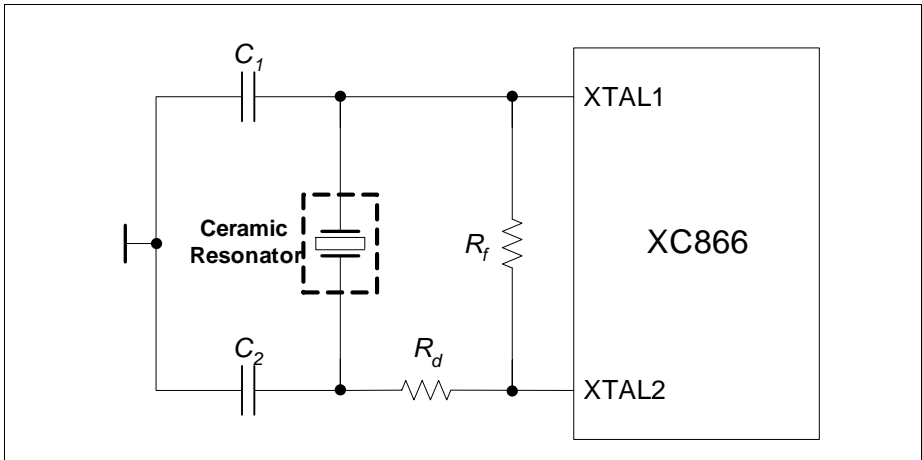


Figure 23 Recommended External Ceramic Resonator Circuitry

Note: The manufacturer of the ceramic resonator should check the resonator circuitry and make recommendations for the C_1 , C_2 , R_f and R_d values to be used for stable start-up behavior.

Clock Management

The CGU generates all clock signals required within the microcontroller from a single clock, f_{sys} . During normal system operation, the typical frequencies of the different modules are as follow:

- CPU clock: CCLK, SCLK = 26.7 MHz
- CCU6 clock: FCLK = 26.7 MHz
- Other peripherals: PCLK = 26.7 MHz
- Flash Interface clock: CCLK3 = 80 MHz and CCLK = 26.7 MHz

In addition, the oscillator clock is output to pin CLKOUT. **Figure 24** shows the clock distribution of the XC866.

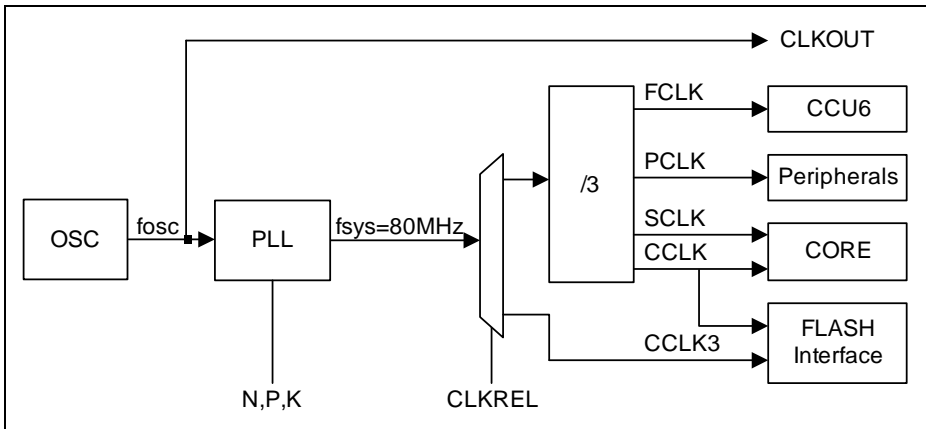


Figure 24 Clock Generation from f_{sys}

For power saving purposes, the clocks may be disabled or slowed down according to **Table 20**.

Table 20 System frequency ($f_{sys} = 80 \text{ MHz}$)

Power Saving Mode	Action
Idle	Clock to the CPU is disabled.
Slow-down	Clocks to the CPU and all the peripherals, including CCU6, are divided by a common programmable factor defined by bit field CMCON.CLKREL.
Power-down	Oscillator and PLL are switched off.

Note: Flash programming and erasing can only be performed at $f_{sys} = 80 \text{ MHz}$. However, Flash read access can be performed as long as $f_{sys} \leq 80 \text{ MHz}$.

Power Saving Modes

The power saving modes of the XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see [Figure 25](#)) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

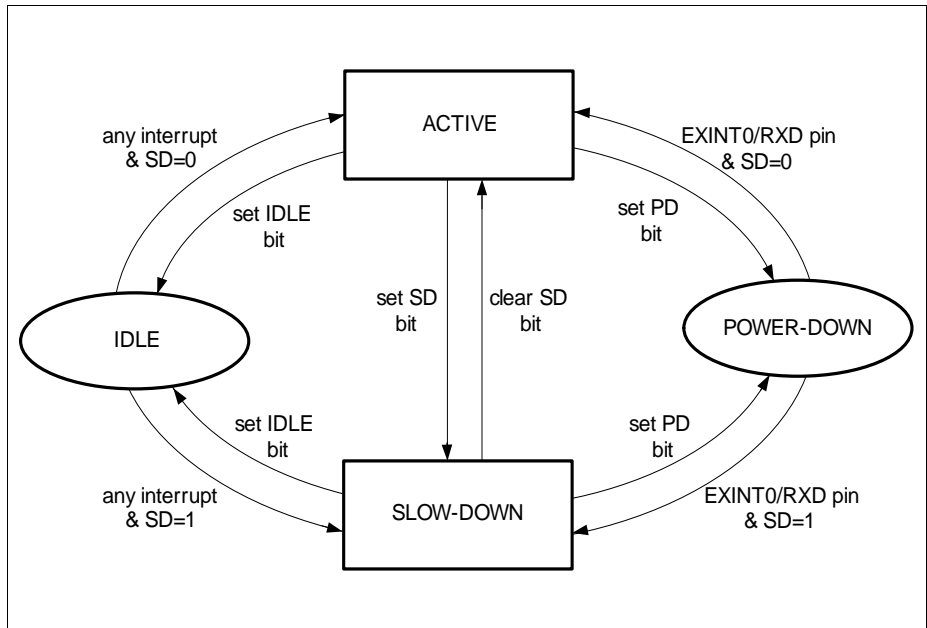


Figure 25 Transition between Power Saving Modes

Watchdog Timer

The Watchdog Timer (WDT) provides a highly reliable and secure way to detect and recover from software or hardware failures. The WDT is a count-up timer that overflows at a regular interval predefined by the user. Each overflow (time-out) triggers an NMI to the CPU and starts a reset prewarning period after which a system reset will be performed. To prevent a system reset, the WDT must be refreshed before an overflow occurs. This requirement necessitates the regular refreshing of the WDT by the CPU, which if fulfilled, confirms that the XC866 system is functioning properly. Hence, an XC866 malfunction will be aborted in a user-specified time period.

Features:

- 16-bit Watchdog Timer
- Programmable reload value for upper 8 bits of timer
- Programmable window boundary
- Selectable input frequency of $f_{PCLK}/2$ or $f_{PCLK}/128$
- Time-out detection with NMI generation and reset prewarning activation (after which a system reset will be performed)

The WDT is a 16-bit timer incremented by a count rate of $f_{PCLK}/2$ or $f_{PCLK}/128$. This 16-bit timer is realized as two concatenated 8-bit timers. The upper 8 bits of the WDT can be preset to a user-programmable value via a watchdog service access in order to modify the watchdog expire time period. The lower 8 bits are reset on each service access. **Figure 26** shows the block diagram of the WDT unit.

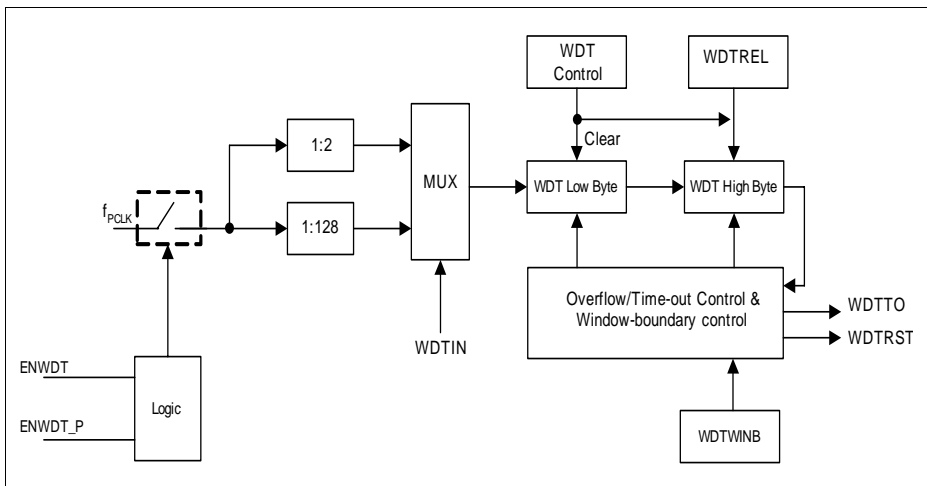


Figure 26 WDT Block Diagram

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert WDTTO) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2⁸). The time period for an overflow of the WDT is programmable in two ways:

- the input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- the reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see [Figure 27](#). This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB should not be smaller than WDTREL.

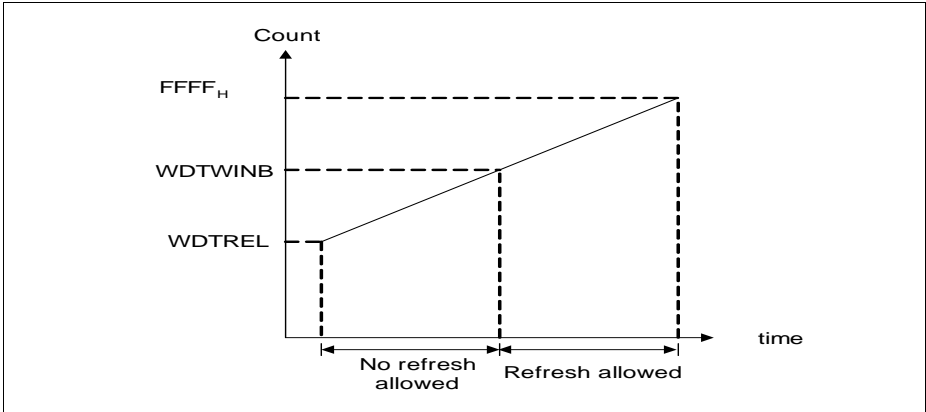


Figure 27 WDT Timing Diagram

Table 21 lists the possible watchdog time range that can be achieved for different module clock frequencies . Some numbers are rounded to 3 significant digits.

Table 21 Watchdog Time Ranges

Reload value in WDTREL	Prescaler for f_{PCLK}	
	2 (WDTIN = 0)	128 (WDTIN = 1)
	26.7 MHz	26.7 MHz
FF _H	19.2 μ s	1.23 ms
7F _H	2.48 ms	159 ms
00 _H	4.92 ms	315 ms

Universal Asynchronous Receiver/Transmitter

The Universal Asynchronous Receiver/Transmitter (UART) provides a full-duplex asynchronous receiver/transmitter, i.e., it can transmit and receive simultaneously. It is also receive-buffered, i.e., it can commence reception of a second byte before a previously received byte has been read from the receive register. However, if the first byte still has not been read by the time reception of the second byte is complete, one of the bytes will be lost.

Features:

- Full-duplex asynchronous modes
 - 8-bit or 9-bit data frames, LSB first
 - fixed or variable baud rate
- Receive buffered
- Multiprocessor communication
- Interrupt generation on the completion of a data transmission or reception

The UART can operate in three asynchronous modes as shown in [Table 22](#). Data is transmitted on TXD and received on RXD.

Table 22 UART Modes

Operating Mode	Baud Rate
Mode 0: Reserved	–
Mode 1: 8-bit shift UART	Variable
Mode 2: 9-bit shift UART	$f_{PCLK}/32$ or $f_{PCLK}/64$
Mode 3: 9-bit shift UART	Variable

There are several ways to generate the baud rate clock for the serial port, depending on the mode in which it is operating. In mode 2, the baud rate is generated internally based on the UART input clock and can be configured to either $f_{PCLK}/32$ or $f_{PCLK}/64$. The variable baud rate for mode 1 and mode 3 is principally set by the underflow rate of the dedicated baud-rate generator.

Baud-Rate Generator

The XC866 provides a dedicated baud-rate generator to generate the baud rate for the UART module, see [Figure 28](#). It has programmable 8-bit reload value and 3-bit prescaler. The baud-rate generator is clocked with f_{DIV} that is derived via a prescaler from the input clock f_{PCLK} . The baud rate timer counts downwards and each underflow of the timer provides one clock pulse to the serial channel.

The baud rate provided by the baud-rate generator depends on the following:

- Input clock f_{PCLK}
- Prescaler (PRE)
- 8-bit reload value (BG)

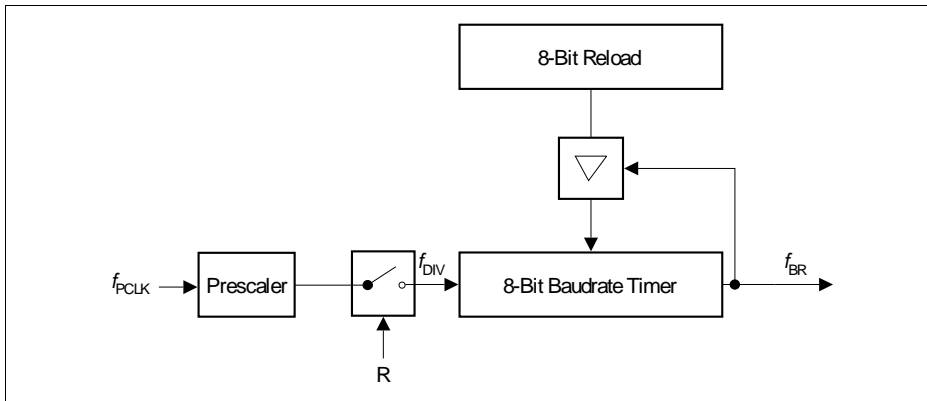


Figure 28 Baud-rate Generator Circuitry

“Baud rate clock” and “baud rate” must be distinguished from each other. The serial interface requires a clock rate that is 16 times the baud rate for internal synchronization. Therefore, the baud-rate generator must provide a “baud rate clock” to the serial interface where it is divided by 16 to obtain the actual “baud rate”. The abbreviations f_{BR} and f_{PCLK} refer to the baud rate clock frequency and input clock frequency respectively. The following formula includes the factor and calculates the final baud rate.

$$\text{baud rate} = \frac{f_{BR}}{16} = \frac{f_{PCLK}}{16 \times \text{PRE} \times (\text{BG} + 1)} \quad \text{where } \text{PRE} \times (\text{BG} + 1) > 1$$

For the XC866, the maximum achievable baud rate for a module clock of 26.7 MHz is 0.83 MBaud. [Table 23](#) lists various commonly used baud rates together with the required reload values and the deviation errors compared to the intended baud rate.

Table 23 Typical Baud Rates of UART

Baud rate ($f_{PCLK} = 26.7 \text{ MHz}$)	PRE	BG	Deviation Error
19.2 kBaud	1	86 (56_H)	-0.22 %
9600 Baud	1	173 (AD_H)	-0.22 %
4800 Baud	2	173 (AD_H)	-0.22 %
2400 Baud	4	173 (AD_H)	-0.22 %

LIN Protocol

The UART can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multiple-slave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in **Figure 29**. The frame consists of the:

- header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- response time
- data bytes (according to UART protocol)
- checksum

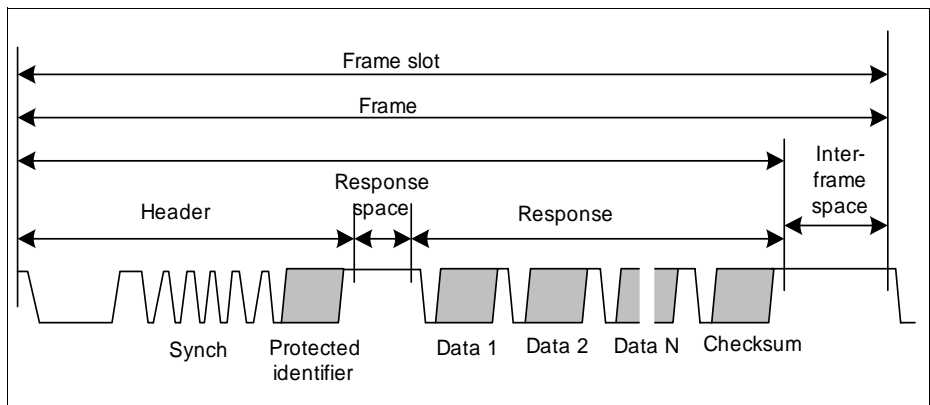


Figure 29 Structure of LIN Frame

High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features:

- Master and slave mode operation
 - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
 - Programmable number of data bits: 2 to 8 bits
 - Programmable shift direction: LSB or MSB shift first
 - Programmable clock polarity: idle low or high state for the shift clock
 - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
 - On a transmitter empty condition
 - On a receiver full condition
 - On an error condition (receive, phase, baud rate, transmit error)

Data is transmitted or received on lines TXD and RXD, which are normally connected to the pins MTSR (Master Transmit/Slave Receive) and MRST (Master Receive/Slave Transmit). The clock signal is output via line MS_CLK (Master Serial Shift Clock) or input via line SS_CLK (Slave Serial Shift Clock). Both lines are normally connected to the pin SCLK. Transmission and reception of data are double-buffered.

Figure 30 shows the block diagram of the SSC.

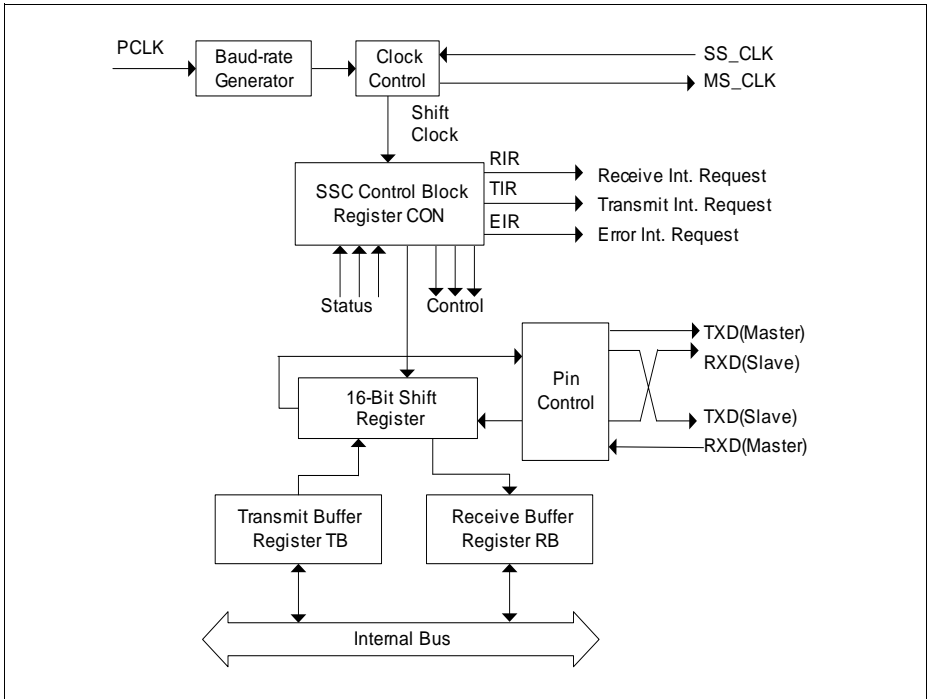


Figure 30 SSC Block Diagram

Timer 0 and Timer 1

Timers 0 and 1 are count-up timers which are incremented every machine cycle, or in terms of the input clock, every 2 PCLK cycles. They are fully compatible and can be configured in four different operating modes for use in a variety of applications, see [Table 24](#). In modes 0, 1 and 2, the two timers operate independently, but in mode 3, their functions are specialized.

Table 24 Timer 0 and Timer 1 Modes

Mode	Operation
0	<p>13-bit timer The timer is essentially an 8-bit counter with a divide-by-32 prescaler. This mode is included solely for compatibility with Intel 8048 devices.</p>
1	<p>16-bit timer The timer registers, TLx and THx, are concatenated to form a 16-bit counter.</p>
2	<p>8-bit timer with auto-reload The timer register TLx is reloaded with a user-defined 8-bit value in THx upon overflow.</p>
3	<p>Timer 0 operates as two 8-bit timers The timer registers, TL0 and TH0, operate as two separate 8-bit counters. Timer 1 is halted and retains its count even if enabled.</p>

Timer 2

Timer 2 is a 16-bit general purpose timer (THL2) that has two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode. If the prescaler is disabled, Timer 2 counts with an input clock of PCLK/12. Timer 2 continues counting as long as it is enabled.

Table 25 Timer 2 Modes

Mode	Description
Auto-reload	<p>Up/Down Count Disabled</p> <ul style="list-style-type: none"> • Count up only • Start counting from 16-bit reload value, overflow at FFFF_H • Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well • Programmable reload value in register RC2 • Interrupt is generated with reload event
	<p>Up/Down Count Enabled</p> <ul style="list-style-type: none"> • Count up or down, direction determined by level at input pin T2EX • No interrupt is generated • Count up <ul style="list-style-type: none"> – Start counting from 16-bit reload value, overflow at FFFF_H – Reload event triggered by overflow condition – Programmable reload value in register RC2 • Count down <ul style="list-style-type: none"> – Start counting from FFFF_H, underflow at value defined in register RC2 – Reload event triggered by underflow condition – Reload value fixed at FFFF_H
Channel capture	<ul style="list-style-type: none"> • Count up only • Start counting from 0000_H, overflow at FFFF_H • Reload event triggered by overflow condition • Reload value fixed at 0000_H • Capture event triggered by falling/rising edge at pin T2EX • Captured timer value stored in register RC2 • Interrupt is generated with reload or capture event

Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features:

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

Timer T13 Features:

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features:

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

The block diagram of the CCU6 module is shown in **Figure 31**.

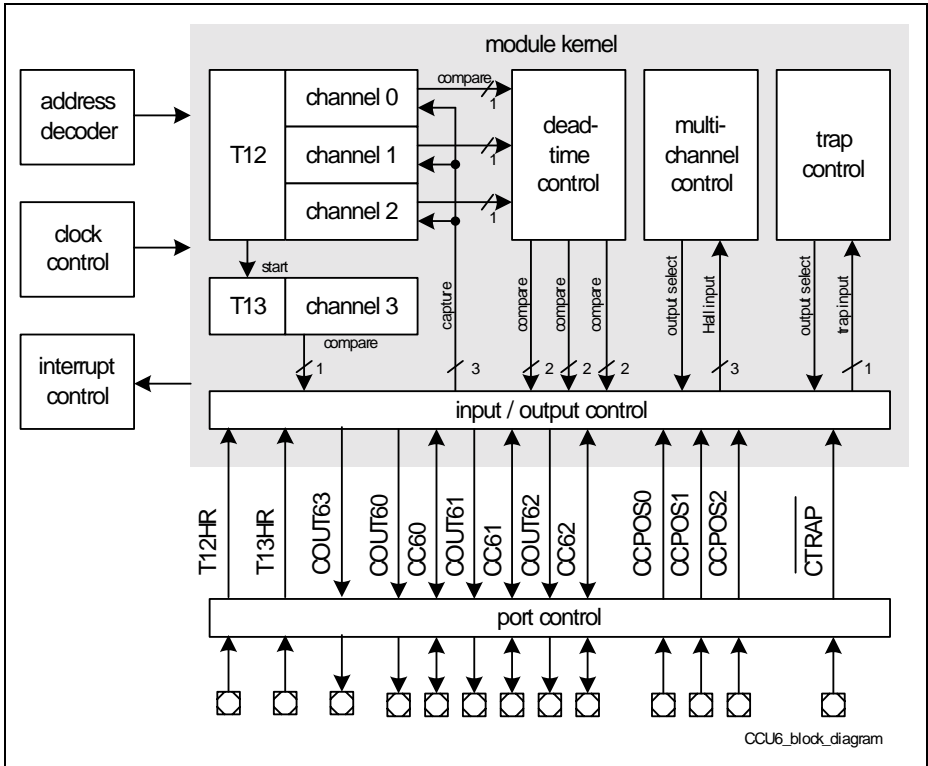


Figure 31 CCU6 Block Diagram

Analog-to-Digital Converter

The XC866 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features:

- Successive approximation
- 8-bit or 10-bit resolution
(TUE of ± 1 LSB and ± 2 LSB, respectively)
- Eight analog channels
- Four independent result registers
(configurable for FIFO functionality)
- Result data protection for slow CPU access
(wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- Limit checking for conversion results
- Data reduction filter
(accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- Flexible interrupt generation with configurable service nodes
- Programmable sample time
- Programmable clock divider
- Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- Low power modes

ADC Clocking Scheme

A common module clock f_{ADC} generates the various clock signals used by the analog and digital parts of the ADC module:

- f_{ADCA} is input clock for the analog part.
- f_{ADCI} is internal clock for the analog part (defines the time base for conversion length and the sample time). This clock is generated internally in the analog part, based on the input clock f_{ADCA} to generate a correct duty cycle for the analog components.
- f_{ADCD} is input clock for the digital part.

The internal clock for the analog part f_{ADCI} is limited to a maximum frequency of 10 MHz. Therefore, the ADC clock prescaler must be programmed to a value that ensures f_{ADCI} does not exceed 10 MHz. The prescaler ratio is selected by bit field CTC in register GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.

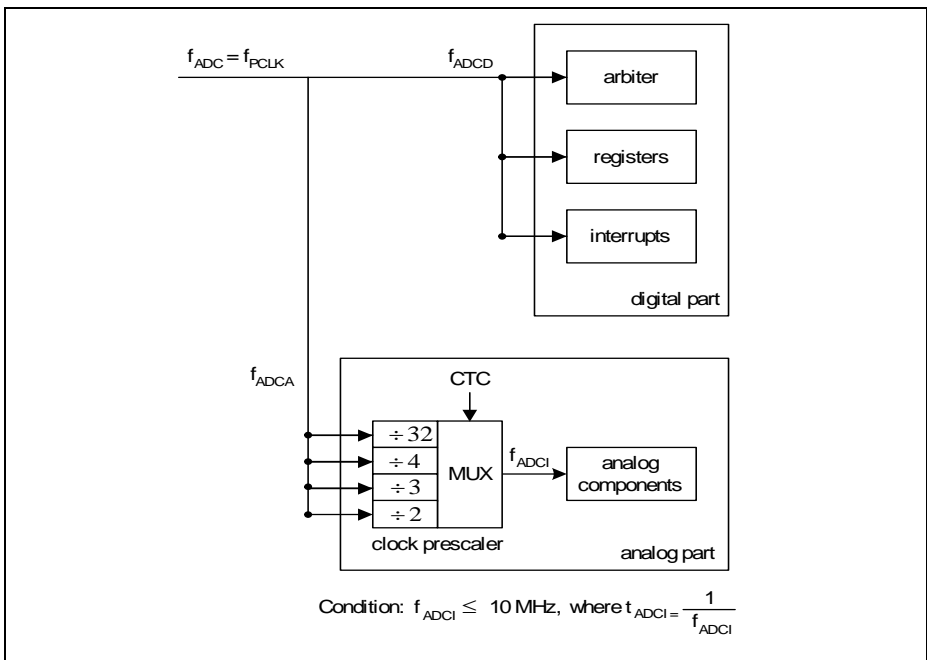


Figure 32 Clocking Scheme

For module clock $f_{ADC} = 26.7$ MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 26**.

Table 26 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
26.7 MHz	00 _B	÷ 2	13.3 MHz (N.A)
	01 _B	÷ 3	8.9 MHz
	10 _B	÷ 4	6.7 MHz
	11 _B (default)	÷ 32	833.3 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 26.7 MHz. During slow-down mode where f_{ADC} may be reduced to 13.3 MHz, 6.7 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})

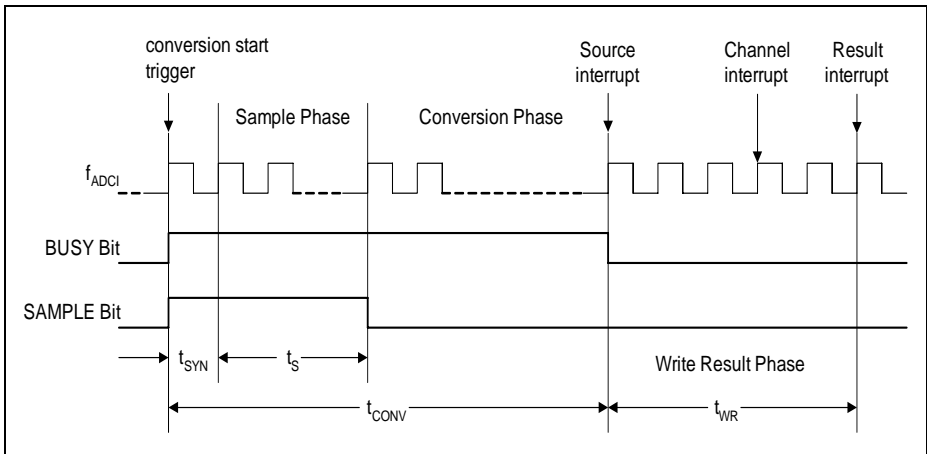


Figure 33 Conversion Timing

On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- use the built-in debug functionality of the XC800 Core
- add a minimum of hardware overhead
- provide support for most of the operations by a Monitor Program
- use standard interfaces to communicate with the Host (a Debugger)

Features:

- Set breakpoints on instruction address and within a specified address range
- Set breakpoints on internal RAM address
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks
- Step through the program code

The OCDS functional blocks are shown in [Figure 34](#). The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals. After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack). The OCDS system is accessed through the JTAG¹⁾, which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after XC866 has been started in OCDS mode.

¹⁾ The pins of the JTAG port can be assigned to either Port 0 (primary) or Ports 1 and 2 (secondary). User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

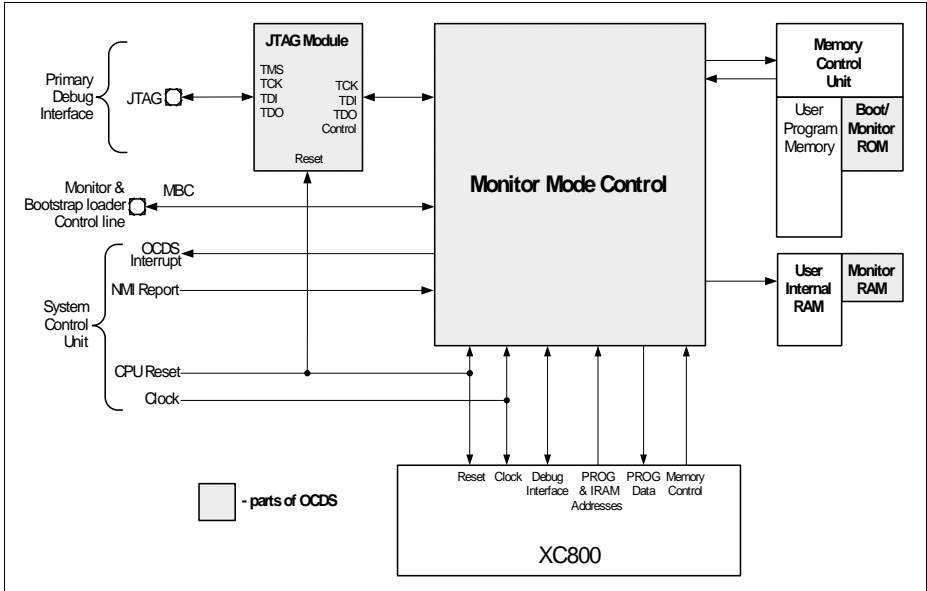


Figure 34 OCDS Block Diagram

JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04_H), and the same is also true immediately after reset.

The JTAG ID register contents for the XC866 Flash devices are given in [Table 27](#).

Table 27 JTAG ID Summary

Device Type	Device Name	JTAG ID
Flash	XC866L-4FR	1010 0083 _H
	XC866-4FR	100F 5083 _H
	XC866L-2FR	1010 2083 _H
	XC866-2FR	1010 1083 _H

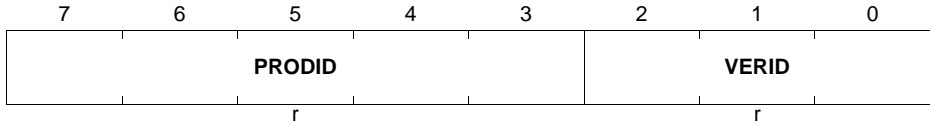
Identification Register

The XC866 identity register is located at Page 1 of address B3_H.

ID

Identity Register

Reset Value: 0000 0001_B



Field	Bits	Type	Description
VERID	[2:0]	r	Version ID 001 _B
PRODID	[7:3]	r	Product ID 00000 _B

DC Characteristic Targets

Parameter Interpretation

The parameters described in the following pages represent, in part, the characteristics of the XC866, and in part, its demands on the system. To aid the correct interpretation of the parameters when making design decisions, their nature is indicated in the column "Symbol":

CC (Controller Characteristics):

The logic of the XC866 will provide signals with the respective timing characteristics.

SR (System Requirement):

The external system must provide signals with the respective timing characteristics to the XC866.

Power Sequencing

TBD

Absolute Maximum Rating Targets

Maximum ratings are the extreme limits to which the XC866 can be subjected to without permanent damage.

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Ambient temperature	T_A	-40	125	°C	under bias
Storage temperature	T_{ST}	-65	150	°C	
Junction temperature	T_J	-40	150	°C	under bias
Voltage on power supply pin with respect to V_{SS}	V_{DDP}	-0.5	6	V	
Input current on any pin during overload condition	I_{IN}	–	10	mA	
Absolute sum of all input currents during overload condition	ΣI_{IN}	–	tbd	mA	
Power dissipation	P_D	–	tbd	W	

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pin with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

Operating Condition Targets

The following operating conditions must not be exceeded in order to ensure correct operation of the XC866. All parameters mentioned in the following table refer to these operating conditions.

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		min.	max.		
Digital supply voltage	V_{DDP}	4.5	5.5	V	5V range
		3.0	4.5	V	3.3V range
Digital ground voltage	V_{SS}	0		V	

Input/Output Characteristic Targets
 $V_{SS} = 0\text{ V}; T_A = -40\text{ }^\circ\text{C to } +125\text{ }^\circ\text{C};$

Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
$V_{DDP} = 5\text{ V Range}$					
Output low voltage	V_{OL} CC	–	1.0	V	$I_{OL} = 15\text{ mA}$
		–	0.4	V	$I_{OL} = 5\text{ mA}$
Output high voltage	V_{OH} CC	$V_{DDP} - 1.0$	–	V	$I_{OH} = -15\text{ mA}$
		$V_{DDP} - 0.4$	–	V	$I_{OH} = -5\text{ mA}$
Input low voltage	V_{IL} SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode
Input high voltage	V_{IH} SR	$0.7 \times V_{DDP}$	–	V	CMOS Mode
Input Hysteresis ¹⁾	HYS CC	$0.08 \times V_{DDP}$	–	mV	CMOS Mode
Pull-up current	I_{PUH} SR	–	-10	μA	$V_{IH, \min}$
		-150	–	μA	$V_{IL, \max}$
Pull-down current	I_{PDL} SR	–	10	μA	$V_{IL, \max}$
		150	–	μA	$V_{IH, \min}$
Input leakage current ²⁾	I_{OZ1} CC	–	500	nA	$0 < V_{IN} < V_{DDP}$
Absolute sum of overload currents	$\Sigma I_{OVL} $	–	50	mA	³⁾
	SR				
$V_{DDP} = 3.3\text{ V Range}$					
Output low voltage	V_{OL} CC	–	1.0	V	$I_{OL} = 10\text{ mA}$
		–	0.4	V	$I_{OL} = 2.5\text{ mA}$
Output high voltage	V_{OH} CC	$V_{DDP} - 1.0$	–	V	$I_{OH} = -8\text{ mA}$
		$V_{DDP} - 0.4$	–	V	$I_{OH} = -2.5\text{ mA}$
Input low voltage	V_{IL} SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode

$V_{SS} = 0\text{ V}; T_A = -40\text{ }^\circ\text{C to } +125\text{ }^\circ\text{C};$

Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
Input high voltage	V_{IH} SR	$0.7 \times V_{DDP}$	–	V	CMOS Mode
Input Hysteresis ¹⁾	HYS CC	$0.03 \times V_{DDP}$	–	mV	CMOS Mode
Pull-up current	I_{PUH} SR	–	-5	μA	$V_{IH,min}$
		-50	–	μA	$V_{IL,max}$
Pull-down current	I_{PDL} SR	–	5	μA	$V_{IL,max}$
		50	–	μA	$V_{IH,min}$
Input leakage current ²⁾	I_{OZ1} CC	–	500	nA	$0 < V_{IN} < V_{DDP}$
Absolute sum of overload currents	$\Sigma I_{OV} $ SR	–	50	mA	³⁾

¹⁾ Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

²⁾ I_{OZ1} verified by simulation of the NMOS and PMOS output driver. ESD components are not simulated. Leakage current of ESD components are not part of the defined leakage current.

³⁾ Not 100% tested, verified by design/characterization.

AC Characteristic Targets

Output Rise/Fall Times

$T_A = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
$V_{DDP} = 5V$ Range					
Rise/fall times ^{1) 2)}	t_R, t_F	–	5	ns	20 pF. ³⁾
$V_{DDP} = 3.3V$ Range					
Rise/fall times ^{1) 2)}	t_R, t_F	–	7	ns	20 pF. ⁴⁾

1) Rise/Fall time measurements are taken with 10% - 90% of the pad supply.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) Additional rise/fall time valid for $C_L = 20\text{pF} - 100\text{pF}$ @ 0.125 ns/pF .

4) Additional rise/fall time valid for $C_L = 20\text{pF} - 100\text{pF}$ @ 0.225 ns/pF .

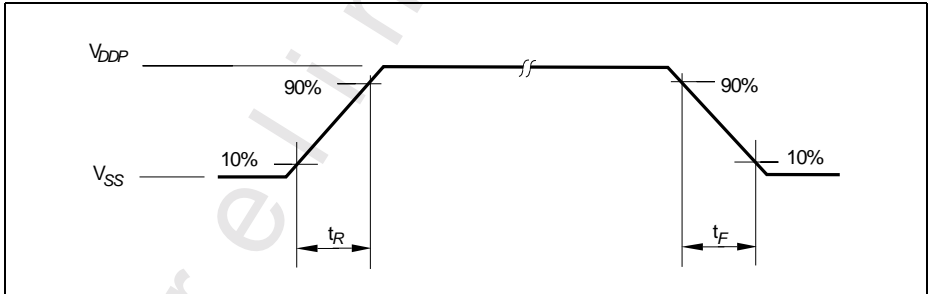


Figure 35 Rise/Fall Times Parameters

Power and Reset Timing

Parameter	Symbol	Limit Values			Unit
		min.	typ.	max.	
V _{DDP} start-up time	$t_{VDDPS\ CC}$	–	–	tbd	us
V _{DD} settle down time	$t_{VDDS\ CC}$	–	–	tbd	us
On-Chip Oscillator start-up time	$t_{OSCS\ CC}$	–	–	500	ns
PLL lock in time	$t_{LOCK\ CC}$	–	–	200	us
Flash Ramp Down time	$t_{RAMPD\ SR}$	–	160	–	us

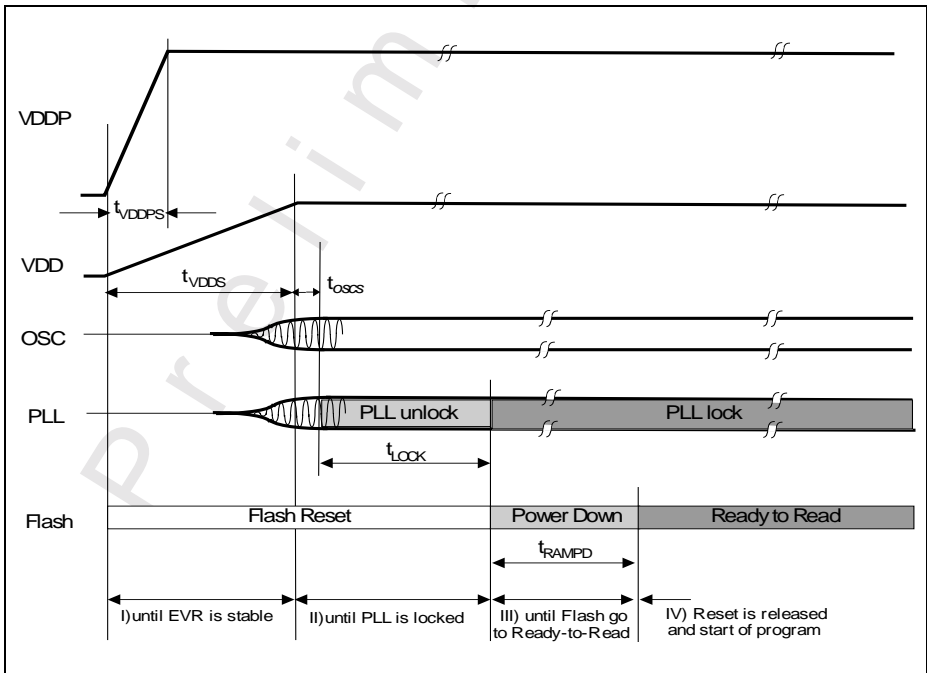


Figure 36 Reset Timing

JTAG Timing

(Operating Conditions apply; $C_L = 50$ pF)

Parameter	Symbol	Limits		Unit
		min	max	
TCK clock period	t_{TCK} SR	50	–	ns
TCK high time	t_1 SR	20	–	ns
TCK low time	t_2 SR	20	–	ns
TCK clock rise time	t_3 SR	–	8	ns
TCK clock fall time	t_4 SR	–	8	ns

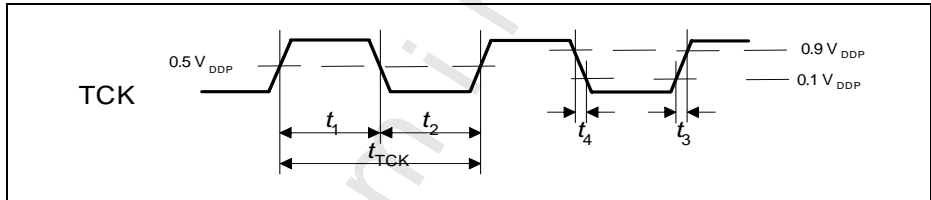


Figure 37 TCK Clock Timing

Parameter	Symbol	Limits		Unit
		min	max	
TMS setup to TCK ↗	t_1 SR	8.0	–	ns
TMS hold to TCK ↘	t_2 SR	4.0	–	ns
TDI setup to TCK ↗	t_1 SR	11.0	–	ns
TDI hold to TCK ↘	t_2 SR	6.0	–	ns
TDO valid output from TCK ↘	t_3 CC	–	tbd	ns
TDO high impedance to valid output from TCK ↘	t_4 CC	–	tbd	ns
TDO valid output to high impedance from TCK ↘	t_5 CC	–	tbd	ns

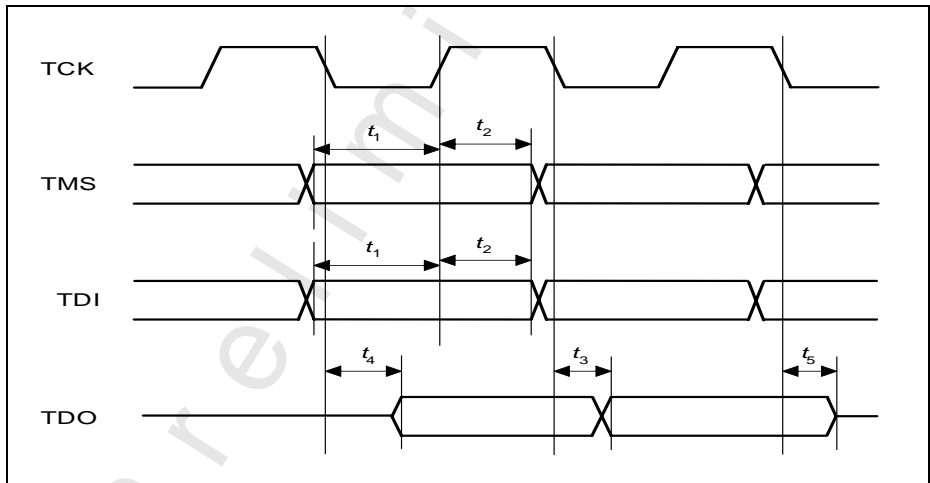


Figure 38 JTAG Timing

SSC Master Mode Timing

(Operating Conditions apply; $C_L = 50$ pF)

Parameter	Symbol	Limit Values		Unit
		min.	max.	
SCLK clock frequency	$1/t_{SCLK}$ CC	–	25	MHz
MTSR delay from SCLK ↗	t_1 CC	0	tbd	ns
MRST setup to SCLK ↗	t_2 SR	5	–	ns
MRST hold from SCLK ↗	t_3 SR	5	–	ns

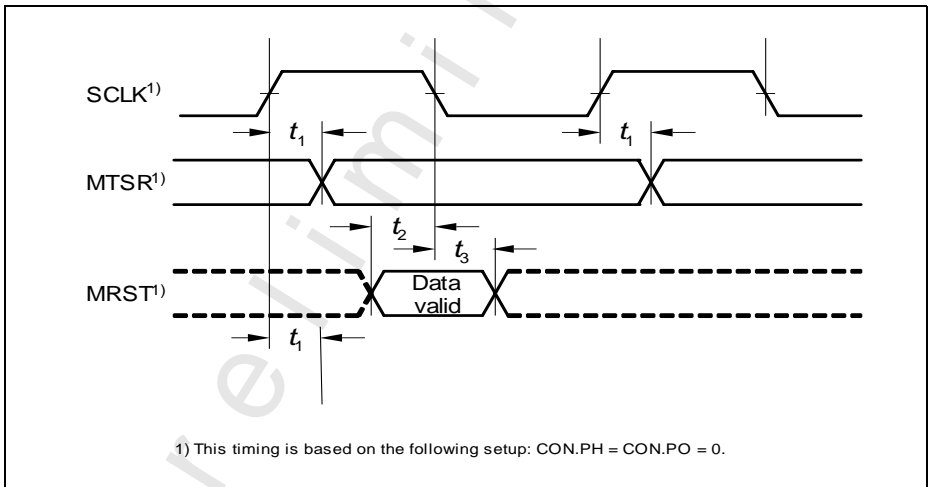


Figure 39 SSC Master Mode Timing

Power Supply Current

Parameter		Symbol	Limit Values		Unit	Test Condition
			typ. ¹⁾	max. ²⁾		
$V_{DDP} = 5V$ Range						
Active Mode	26.7 MHz ³⁾	I_{DDP}	tbd	tbd	mA	4)
Idle Mode	26.7 MHz ³⁾	I_{DDP}	tbd	tbd	mA	5)
Active Mode with slow-down enabled	26.7 MHz ³⁾	I_{DDP}	tbd	tbd	mA	6)
Idle Mode with slow-down enabled	26.7 MHz ³⁾	I_{DDP}	tbd	tbd	mA	7)
Power-Down Mode		I_{PDP}	tbd	tbd	μA	8)

Note:

- 1) The typical I_{DDP} values are periodically measured at $T_A = +25\text{ }^\circ\text{C}$ and $V_{DDP} = 5.0\text{ V}$, but not 100% tested.
- 2) The maximum I_{DDP} values are measured under worst case conditions ($T_A = -40\text{ }^\circ\text{C}$ and $V_{DDP} = 5.5\text{ V}$).
- 3) CPU clock, set by on-chip oscillator of 10 MHz and setting NDIV in PLL_CON to 0010_B.
- 4) I_{DDP} (active mode) is measured with: $\overline{\text{RESET}} = V_{DDP}$.
- 5) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled, $\text{RESET} = V_{DDP}$.
- 6) I_{DDP} (active mode with slow-down mode) is measured with: slow-down clock set to 1/32 of system clock, $\overline{\text{RESET}} = V_{DDP}$.
- 7) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled, slow-down clock set to 1/32 of system clock, $\text{RESET} = V_{DDP}$.
- 8) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}} = V_{DDP}$, $V_{AGND} = V_{SS}$, $\text{RXD}/\text{INT0} = V_{DDP}$.

Parameter		Symbol	Limit Values		Unit	Test Condition
			typ. ¹⁾	max. ²⁾		
V_{DDP} = 3.3V Range						
Active Mode	26.7 MHz ³⁾	I _{DDP}	tbd	tbd	mA	4)
Idle Mode	26.7 MHz ³⁾	I _{DDP}	tbd	tbd	mA	5)
Active Mode with slow-down enabled	26.7 MHz ³⁾	I _{DDP}	tbd	tbd	mA	6)
Idle Mode with slow-down enabled	26.7 MHz ³⁾	I _{DDP}	tbd	tbd	mA	7)
Power-Down Mode		I _{PDP}	tbd	tbd	μA	8)

Note:

- 1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V, but not 100% tested.
- 2) The maximum I_{DDP} values are measured under worst case conditions (T_A = - 40 °C and V_{DDP} = 3.6 V).
- 3) CPU clock, set by on-chip oscillator of 10 MHz and setting NDIV in PLL_CON to 0010_B.
- 4) I_{DDP} (active mode) is measured with: $\overline{\text{RESET}} = V_{\text{DDP}}$.
- 5) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled, $\overline{\text{RESET}} = V_{\text{DDP}}$.
- 6) I_{DDP} (active mode with slow-down mode) is measured with: slow-down clock set to 1/32 of system clock, $\overline{\text{RESET}} = V_{\text{DDP}}$.
- 7) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled, slow-down clock set to 1/32 of system clock, $\overline{\text{RESET}} = V_{\text{DDP}}$.
- 8) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}} = V_{\text{DDP}}$, V_{AGND} = V_{SS}, RXD/INT0 = V_{DDP}.

ADC Characteristic Targets

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (VSS) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

$V_{SS} = 0\text{ V}$; $T_A = -40\text{ °C}$ to $+125\text{ °C}$;

Parameter	Symbol	Limit Values			Unit	Test Conditions/ Remarks
		min.	typ.	max.		
Analog reference voltage	V_{AREF} SR	V_{AGND} + 1	V_{DDP}	V_{DDP} + 0.05	V	
Analog reference ground	V_{AGND} SR	V_{SS} - 0.05	V_{SS}	V_{AREF} - 1	V	
Analog input voltage range	V_{AIN} SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}	–	20	40	MHz	module clock
	f_{ADCI}	–	–	10	MHz	internal analog clock See Page 69
Sample time	t_S CC	$(2 + INPCR0.STC) \times t_{ADCI}$			μs	
Conversion time	t_C CC	See Page 87			μs	
Total unadjusted error	$TUE^1)CC$	–	–	± 1	LSB	8-bit conversion. ²⁾
		–	–	± 2	LSB	10-bit conversion. ²⁾
Switched capacitance at the reference voltage input	C_{AREFSW} CC	–	10	20	pF	2)3)
Switched capacitance at the analog voltage inputs	C_{AINSW} CC	–	5	7	pF	2)4)
Input resistance of the reference input	$R_{AREF}CC$	–	1	2	k Ω	2)
Input resistance of the selected analog channel	R_{AIN} CC	–	1	1.5	k Ω	2)

- 1) TUE is tested at $V_{AREF} = 5.0\text{ V}$, $V_{AGND} = 0\text{ V}$.
- 2) Not subject to production test, verified by design/characterization
- 3) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.
- 4) The sampling capacity of the conversion C-Network is pre-charged to $V_{AREF}/2$ before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than $V_{AREF}/2$.

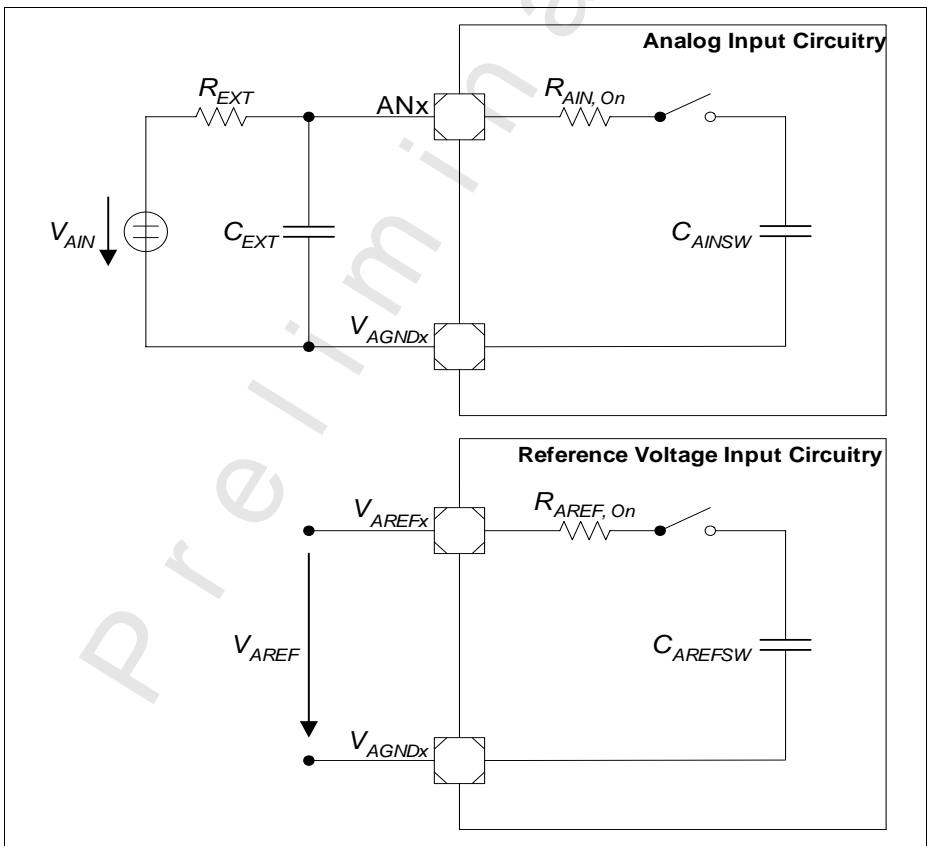


Figure 40 ADC Input Circuits

Conversion Timing

Conversion time, $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$

where

$r = CTC + 2$ for $CTC = 00_B, 01_B$ or 10_B ,

$r = 32$ for $CTC = 11_B$,

CTC = Conversion Time Control (GLOBCTR.CTC),

STC = Sample Time Control (INPCR0.STC),

$n = 8$ or 10 (for 8-bit and 10-bit conversion respectively),

$t_{ADC} = 1 / f_{ADC}$

Package Outline

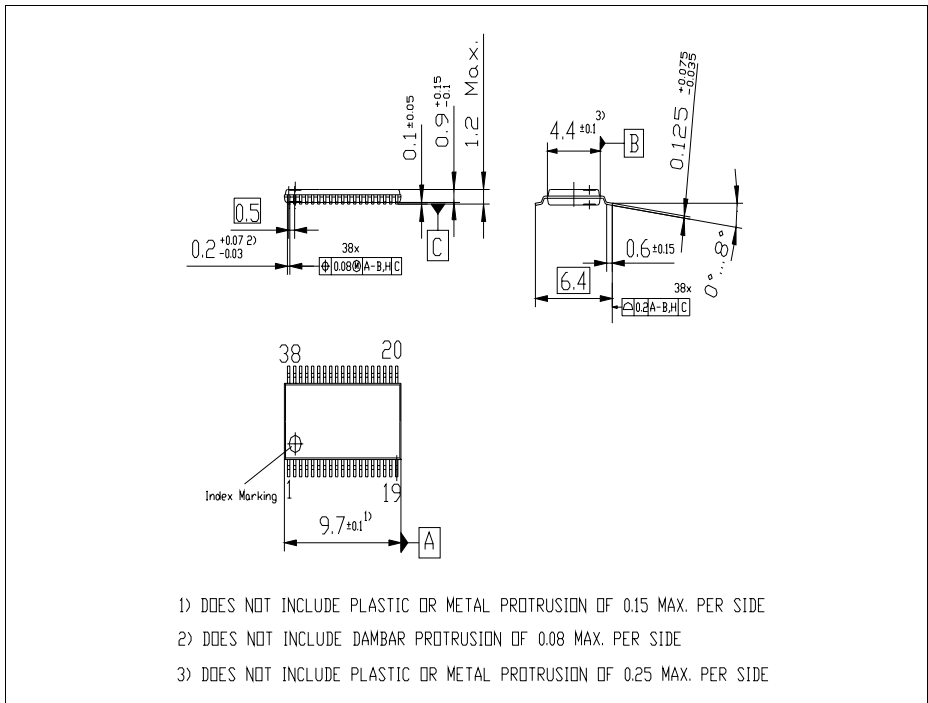


Figure 41 PG-TSSOP-38-3 Package Outline

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